

Simulation and Modeling of Large Microwave and Millimeter-Wave Systems, Part 2

Michael Steer

with

Nikhil Kriplani, Carlos Christofferson
and Shivam Priyadarshi

<http://www.freeda.org>

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Outline

fREEDA™ Modeling Code

Simple device modeling

Noise Modeling

Transistor Model

Quasi-Optical Modeling

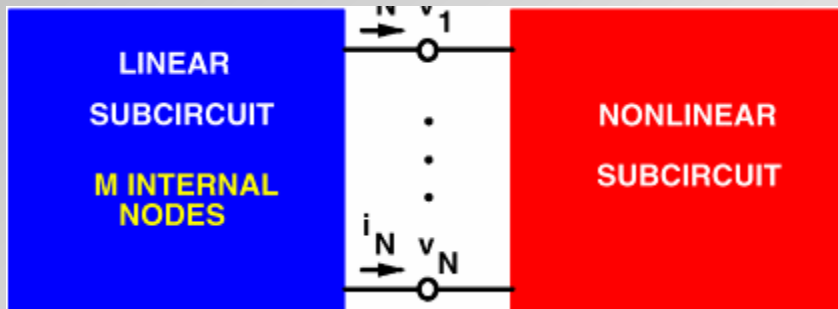
Parallel Circuit Simulation

Distributions

Commercialization

Circuit-Level Behavioral Modeling

Linear Sub-Circuit Behavioral Modeling



Behavioral Model is the Linear Subcircuit Described by

$(M + N) \times (M + N)$ Y Parameters

Reduce to $N \times N$ Y Parameters

Harmonic Balance

Use $N \times N$ Parameters Directly

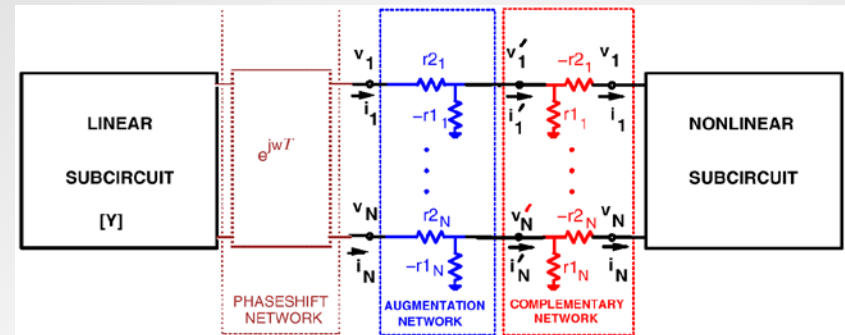
SPICE

Use Impulse Response



or Use Pole-Zero Approximation

Transient Analysis of Microwave Circuit



Behavioral Model is an Impulse Response

Augmentation Network Used to Facilitate Incorporation of Behavioral Model

Frequency and Time Banding

Effect of the augmentation network removed during simulation.

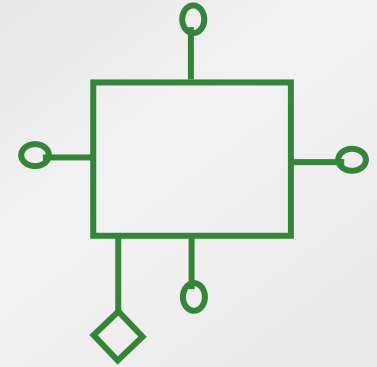
Response of linear network is limited in time and frequency.

Coding Example

Modeling Scope

Can handle

$$y(t) = F \left[\begin{array}{l} x_1(t), \dots, x_n(t), \frac{dx_1(t)}{dt}, \dots, \frac{dx_n(t)}{dt}, \\ \frac{d^2 x_1(t)}{dt^2}, \dots, \frac{d^2 x_n(t)}{dt^2}, \frac{d^3 x_1(t)}{dt^3}, \dots, \frac{d^3 x_n(t)}{dt^3}, \\ x_1(t - \tau_1), \dots, x_n(t - \tau_1) \end{array} \right]$$



Where $y(t)$ is either an $i(t)$ or a $v(t)$.

Also in any type of analysis we want dy/dx The exact derivatives (w.r.t. time or frequency etc.) we want depend on the type of analysis we are doing (transient, wavelet, harmonic balance). The derivatives needed are calculated using ADOL-C under control of the analysis routines. This is why the same model can be used in any type of analysis.

ADOL-C is one of the many support libraries.

Quick Once Over of Element Code

Electro-Thermal Resistor Code

```
// This may look like C code, but it is really -*- C++ -*-
//
// This is an electro-thermal resistor model
//
//          ++++++
//          +   tr   +
//          o-----/\/\/\-----o
//          +           +
//          + *       * +
//          + |       | +
//          ++ | +++++ | ++
//          |         |
//          o         o
//          tref    tout
//
// by Housssam S. Kanj
```

Header files may be included more than once in C++ programs. To avoid multiple declarations of the classes defined in the body of the header file, the definitions in the header file are enclosed by following preprocessor directives:

```
#ifndef Tresistor_h
#define Tresistor_h 1
class Tresistor : public AdolcElement
{
    :
}
#endif
```

Electro-Thermal Resistor Code

```
#include "../network/ElementManager.h"
#include "../network/AdolcElement.h"
#include "../analysis/FreqMNAM.h"
#include "../analysis/TimeMNAM.h"
#include "Tresistor.h"
```

Now we must define the static member variables:

```
// Static members
const unsigned Resistor::n_par = 11;

// Element information
ItemInfo Resistor::einfo = {
    "tr",
    "Tresistor",
    "Houssam S. Kanj",
    DEFAULT_ADDRESS"elements/Resistor.h.html"
};

// Parameter information
ParmInfo Tresistor::pinfo[] = {
    {"r0", "Resistance value (Ohms)", TR_DOUBLE, false},
    {"l", "length (meters)", TR_DOUBLE, false},
    {"w", "width (meters)", TR_DOUBLE, false},
    {"t", "system Temperature (Celsius)", TR_DOUBLE, false},
    {"rsh", "sheet resistance (Ohms/sq)", TR_DOUBLE, false},
    {"defw", "default device width (meters)", TR_DOUBLE, false},
    {"narrow", "narrowing due to side etching (meters)", TR_DOUBLE, false},
    {"tnom", "initial Temperature (Celsius)", TR_DOUBLE, false},
    {"tc1", "Temperature Coefficient (1/Celsius)", TR_DOUBLE, false},
    {"tc2", "Temperature Coefficient (1/Celsius)", TR_DOUBLE, false},
    {"pdr", "Power Dependent Resistor", TR_BOOLEAN, false}
};
```

Evaluation Routine

```

void TResistor::eval(adoublev& x,
                    adoublev& vp, adoublev& ip)
{
    // x[0]: resistor voltage
    // x[1]: temp in deg. Celsius

    vp[0]=x[0];
    vp[1]=x[1]+tnom+273; //vp[1]==tp[1] in Kelvin

    adouble res;
    res = r0 * (one + tc1 * x[1] + tc2 * x[1] * x[1]);
    ip[0] = x[0] / res;
    ip[1] = - x[0] * ip[0]; //ip[1]==pp[0];
}

```

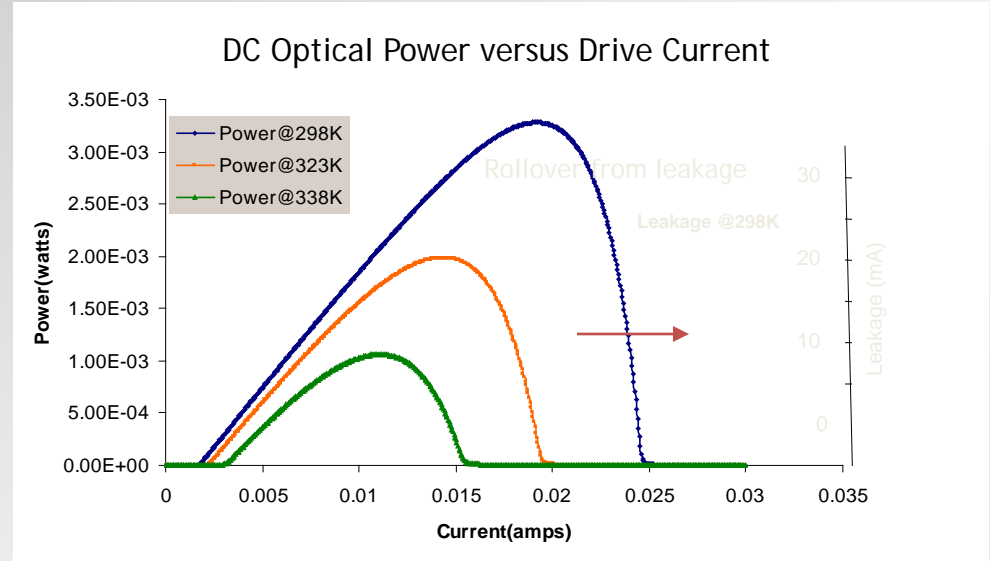
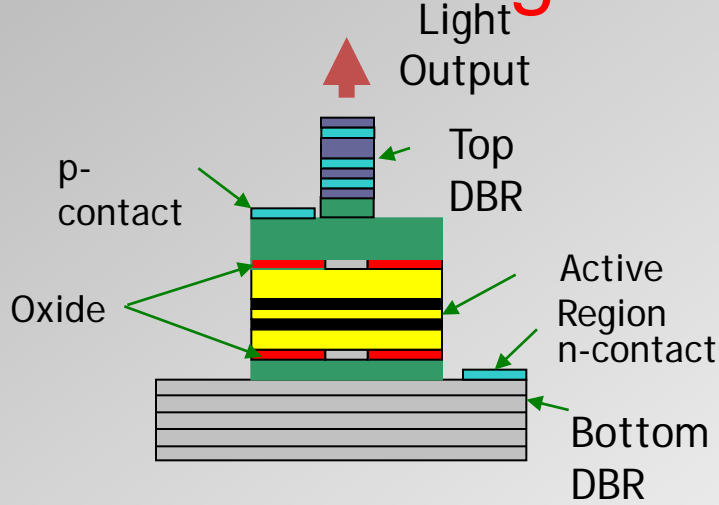
This is the only executable code

The same model close is used in all analyses: DC, Transient; Wavelet; Large Signal Noise, Harmonic balance; Analyses (32 altogether).

**What can be
Modeled that
Could not be
Modeled Before**

VCSEL

VCSEL Modeling



Single Mode Rate Equations

Carrier density

$$dN(t)/dt = \eta_i(I(t) - I_L(T)) / \tau - N(t) / \tau_{nr} - G(T)(N(t) - N_0(T))S(t) / (1 + \epsilon S(t))$$

Photon density

$$dS(t)/dt = -S(t) / \tau_p + \beta N(t) / \tau_r + G(T)(N(t) - N_0(T))S(t) / (1 + \epsilon S(t))$$

Temperature

$$dT(t)/dt = -T(t) / \tau_{th} + (T_0 + (I(t)V(t) - P_0(t))R_{th}) / \tau_{th}$$

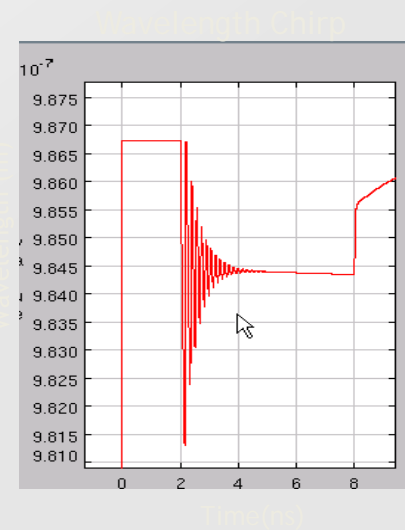
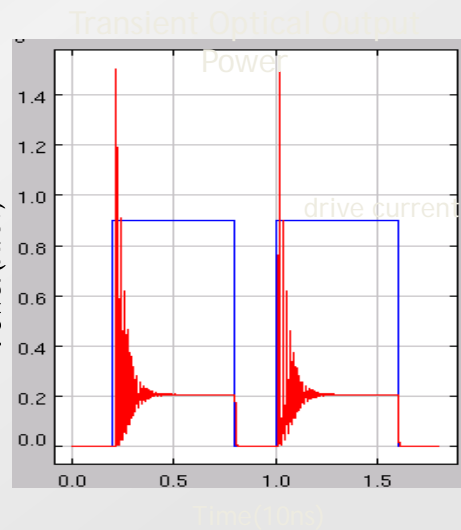
Temperature dependence of Gain and Transparency

$$G(T) = G_0(a_{g0} + a_{g1}T + a_{g2}T^2) / (b_{g0} + b_{g1}T + b_{g2}T^2)$$

$$N_0(T) = N_{t0}(c_{n0} + c_{n1}T + c_{n2}T^2)$$

Leakage Current

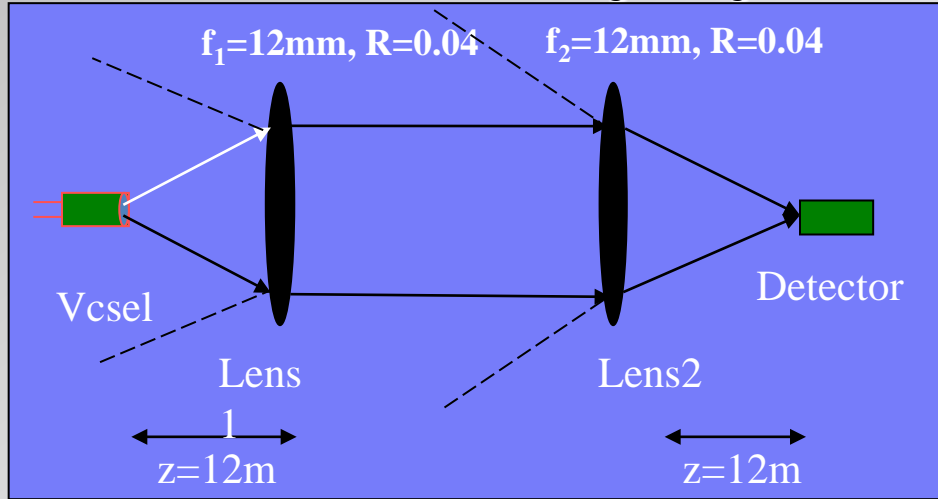
$$I_L = I_{L0} \exp[(-a_0 + a_1 N_0 + a_2 N_0 T - a_3 / N_0) / T]$$



Electro-Optics

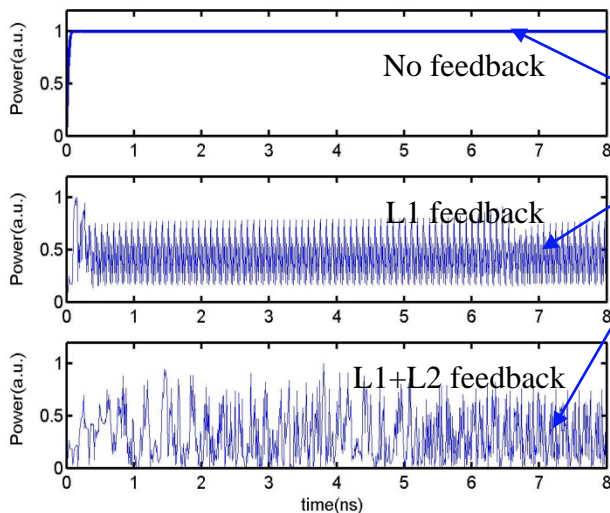
Feedback Results:

- Power and Wavelength degradation due to two components



With:
 Mark Niefeld
 Ravi Pant
 Univ. of Arizona

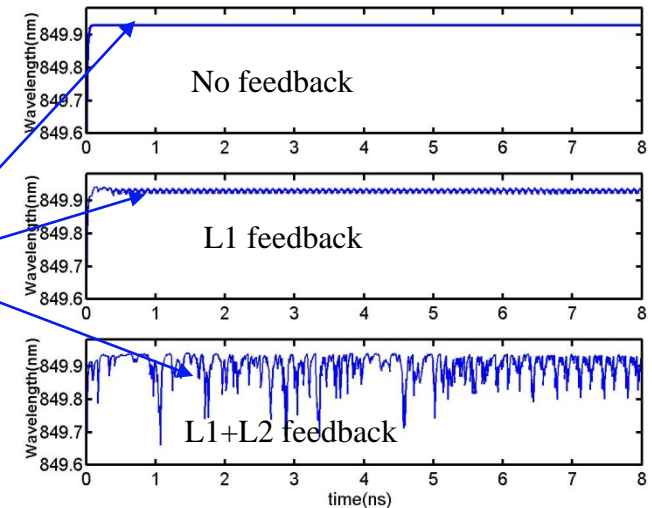
Optical Power



Output power degradation due to single and double lens feedback

Output wavelength degradation due to single and double lens feedback

Wavelength



Code

$$f \left(x(t), \frac{dx}{dt}, \frac{d^2x}{dt^2}, x(t-\tau) \right)$$

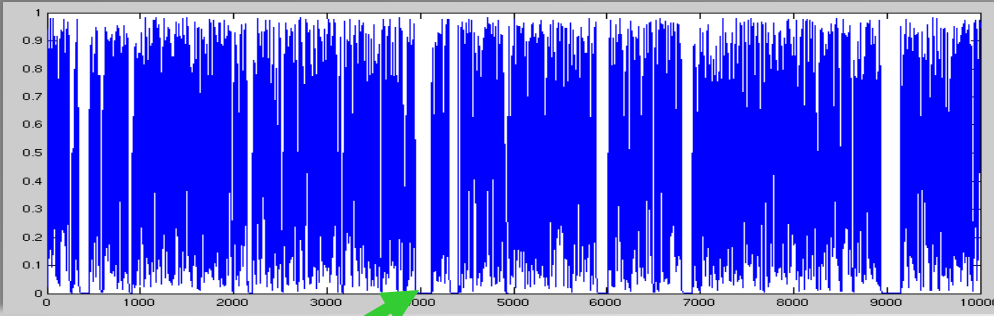
```

void Vcsel::eval(adoublev& x, adoublev& vp, adoublev& ip)
{
    // x[0]: terminal current, I
    // x[1]: photon density, vm0
    // x[2]: carrier density, vn0
    // x[3]: temperature, T
    // x[4]: dI/dt
    // x[5]: dvm0/dt
    // x[6]: dvn0/dt
    // x[7]: dT/dt
    adouble delta = 1e-8;
    adouble zn = 1e7;
    adouble q = 1.6e-19;
    vp[0] = 1.721 + 275*x[0] - 2.439e4*x[0]*x[0] + 1.338e6*x[0]*x[0]*x[0]
            - 4.154e7*x[0]*x[0]*x[0]*x[0] + 6.683e8*x[0]*x[0]*x[0]*x[0]*x[0]
            - 4.296e9*x[0]*x[0]*x[0]*x[0]*x[0]*x[0];
    ip[0] = x[0];
    adouble T = t0 + x[0];
    adouble G = g0 * (ag0 + ag1*T + ag2*T*T)/(bg0 + bg1*T + bg2*T*T);
    adouble Nt = nt0 * (cn0 + cn1*T + cn2*T*T);
    adouble Il = il0 * exp((-a0 + a1*zn*vn0+a2*zn*vn0*T - a3/(zn*vn0))/T);
}

```

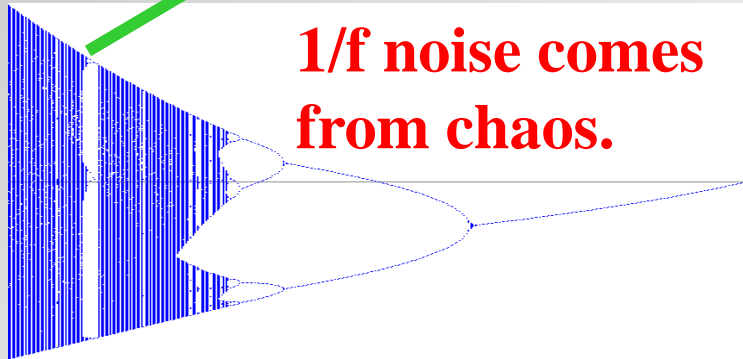
Large Signal Noise Modeling

Flicker Noise



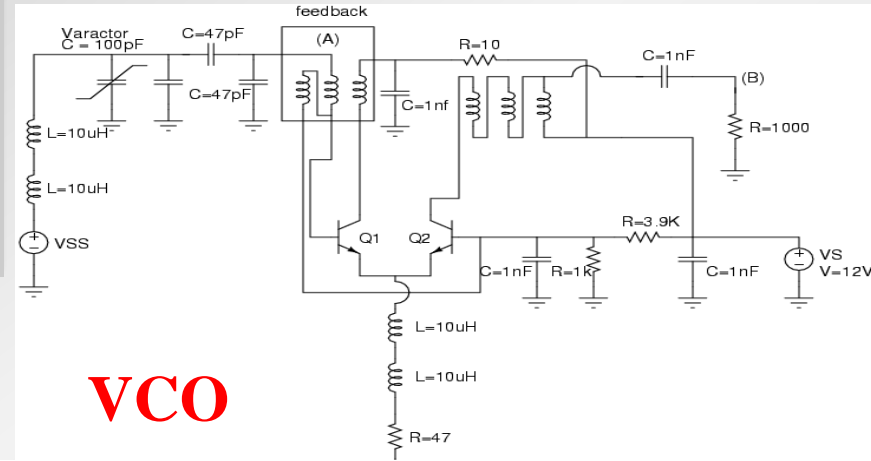
Laminar Regions

1/f noise comes from chaos.

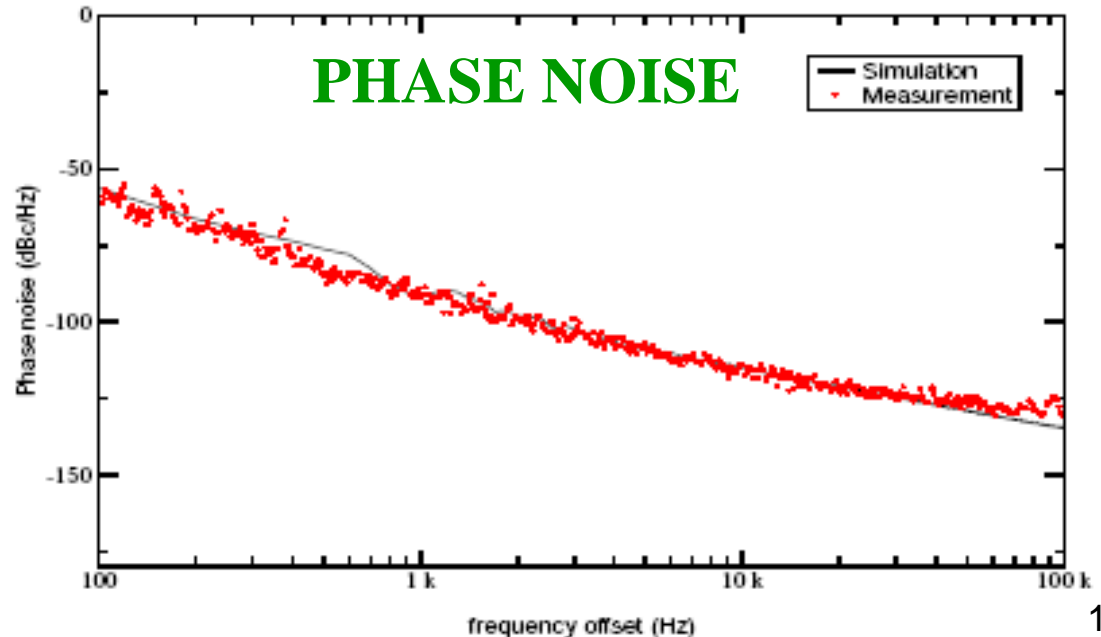


Phase noise modeled in the time domain.

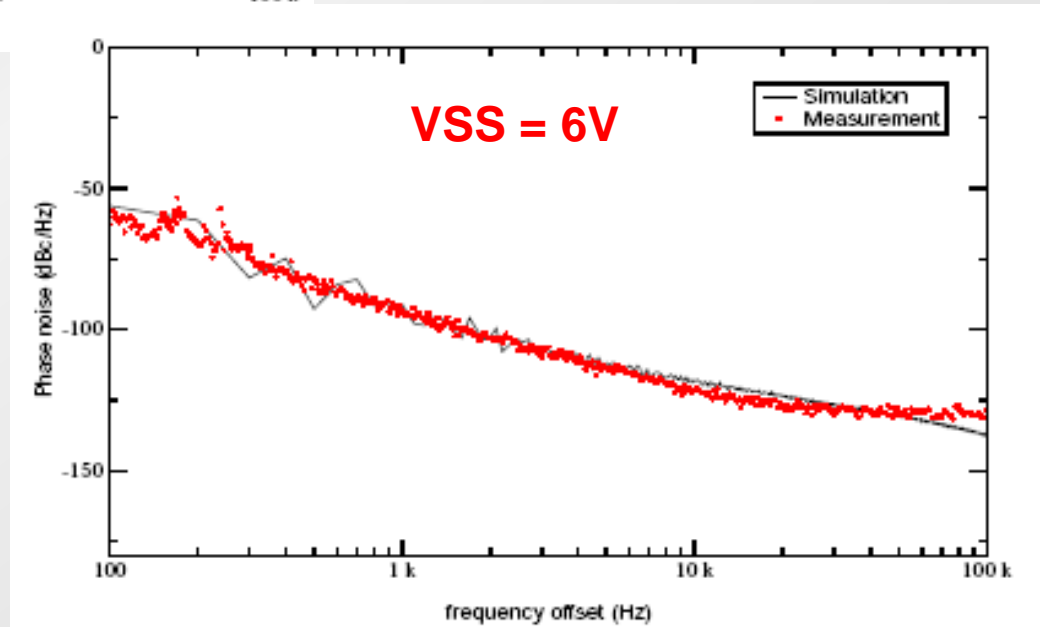
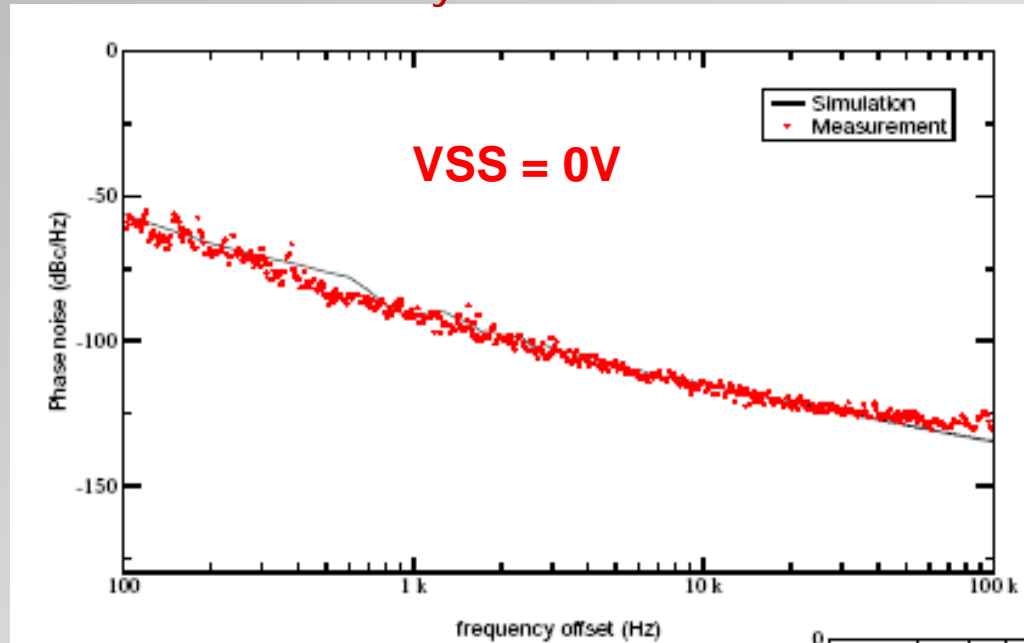
+ Large Signal Noise



VCO

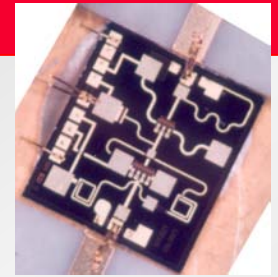


Phase Noise is Fully Predictive

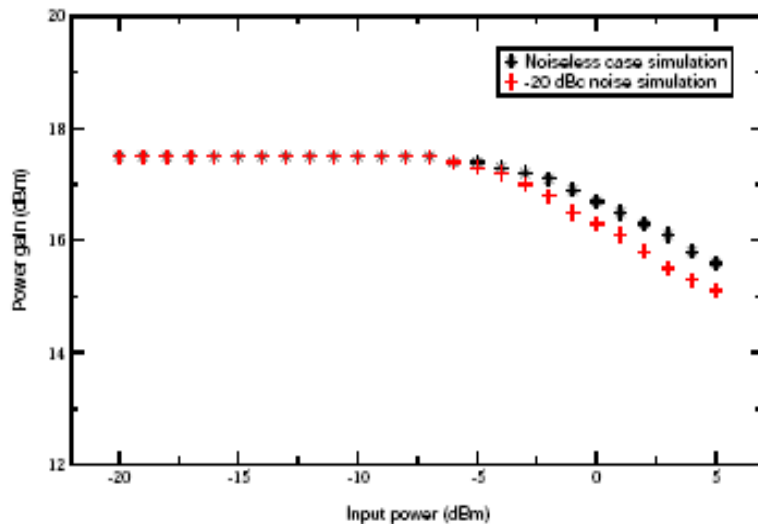
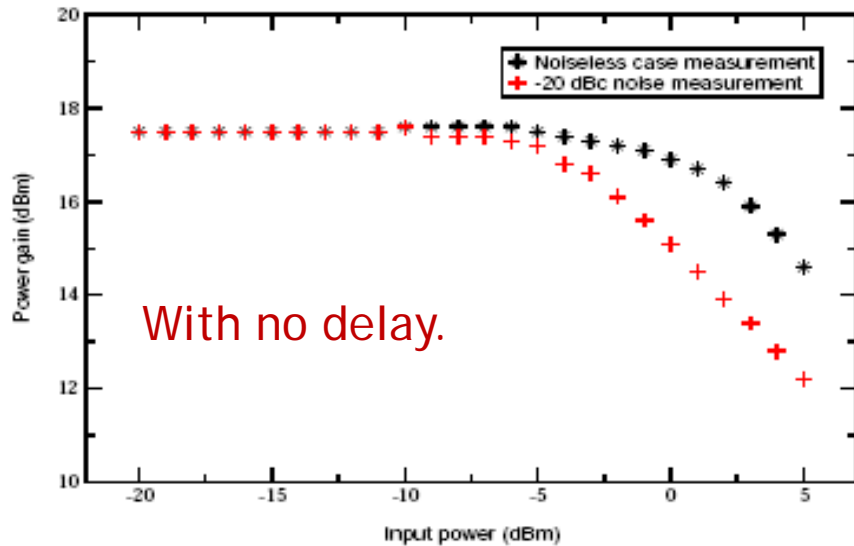


Large Signal Noise

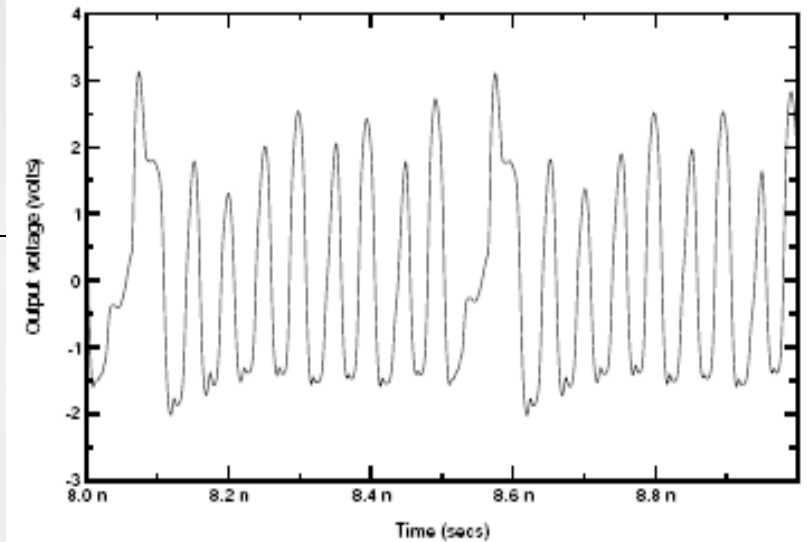
X-band MMIC



Measurement of power gain v/s input power



With 1 ps delay for each transistor



Device 1			
a0 = 0.09910	a1 = 0.08541	a2 = -0.0203	a3 = -0.015
beta = 0.01865	gama = 0.8293	vds0 = 6.494	vt0 = -1.2
vbi = 0.8	cgd0 = 3f	cgs0 = 528.2f	is = 3e-12
nr = 1.2	t = 1e-12	vbd = 12	kf = 1e-9
Device 2			
a0 = 0.1321	a1 = 0.1085	a2 = -0.04804	a3 = -0.03821
beta = 0.03141	gama = 0.7946	vds0 = 5.892	vt0 = -1.2
vbi = 1.5	cgd0 = 4e-15	cgs0 = 695.2f	is = 4e-12
n = 1.2	t = 1e-12	vbd = 12	kf = 1e-9

Modeling Noise

Deterministic differential equation:

$$\frac{dx}{dt} = a(t, x)$$

Stochastic differential equation

$$\frac{d}{dt}X_t = a(t, X_t) + b(t, X_t)\xi_t.$$

The Ito form

- Named after Japanese mathematician K. Ito in the late 40s. He formulated the theory of Stochastic integration.
- Evaluation at the starting point on each interval.
- Requires no estimation of future values.
- Used in models where stochastic processes are assumed purely white.

The Stratonovich form

- Named after Russian engineer R. L. Stratonovich in the mid 60s.
- Evaluation at the mid-point on each interval.
- Requires estimation of future values.
- Used in models where stochastic processes are not purely white.

Either form will produce different end results but are both mathematically “right”.

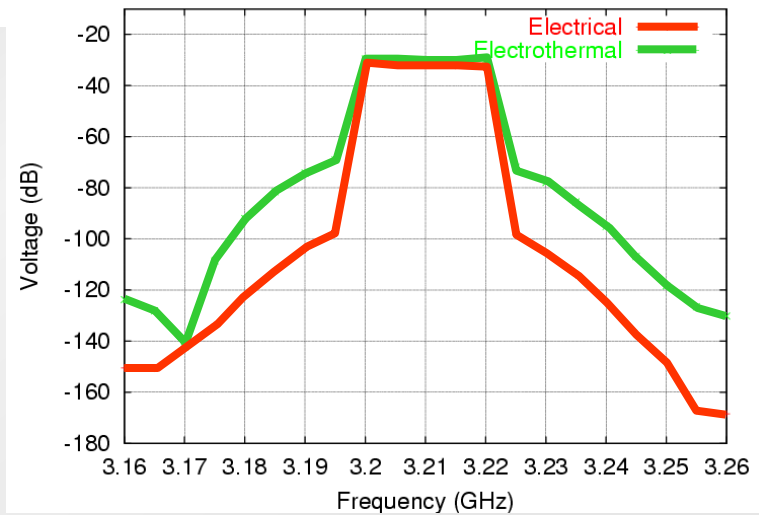
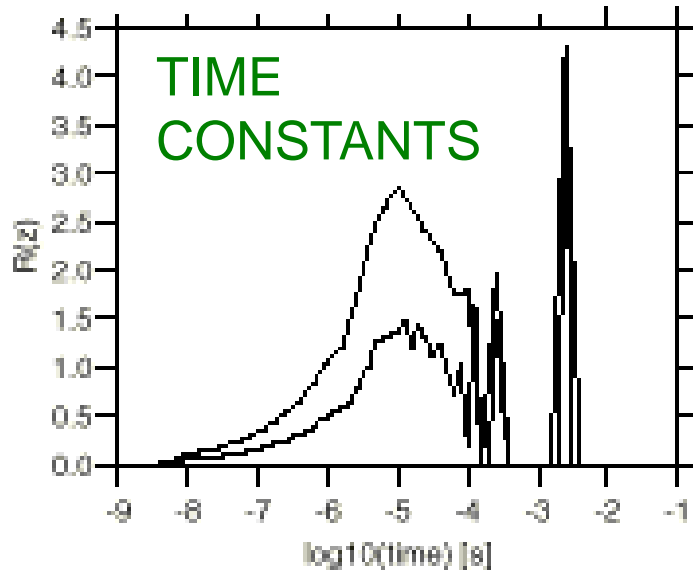
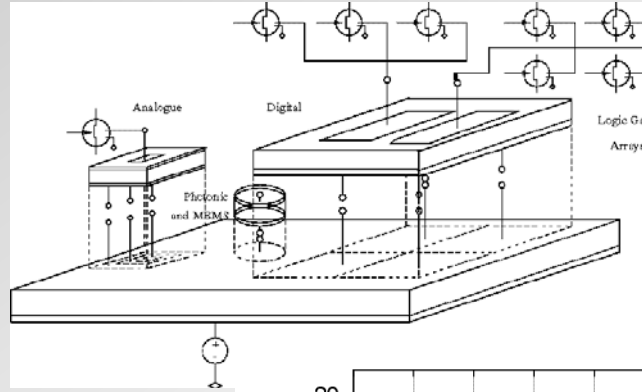
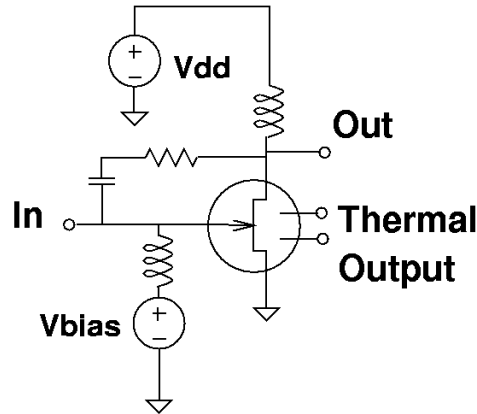
Which form to use is a modeling issue.

The Ito form requires new numerical techniques for solving an SDE. The Stratonovich form can be solved using techniques of classical calculus which is a significant advantage.

Electro-Thermal Physical Transistor Model

Electro-Thermal Modeling of PA

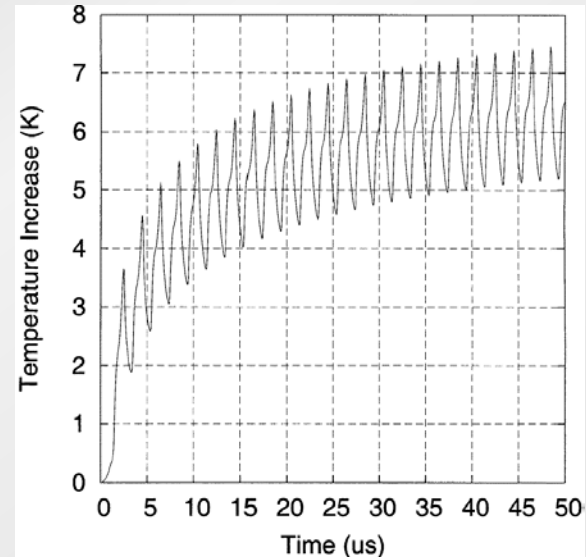
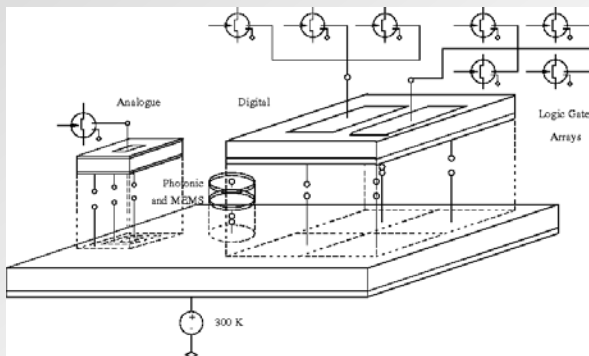
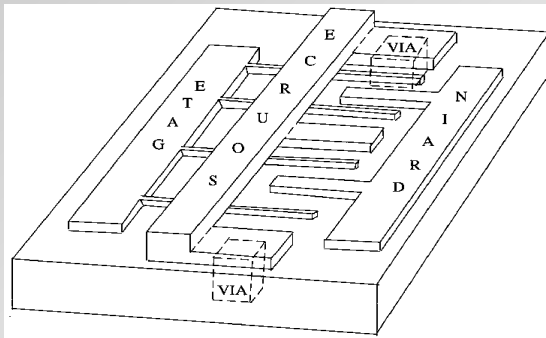
Batty/Snowden
Univ. Leeds



**CONVERT NONLINEAR THERMAL
PROBLEM INTO A LINEAR
PROBLEM
KEY CONCEPT IS TIME DILATION**

The first implementation of a Physical Transistor Model directly into a general purpose simulator: LPM (Leed's Physical Model) (implementation by University of Leeds in fREEDA). This is a full electro-thermal model of MESFETs and pHEMTs. Full device physics.

This can only be done in fREEDA because of state variables and universal error concepts (not just KCL).

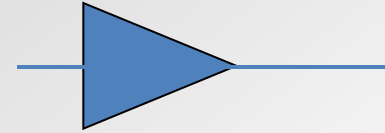


Temperature rise in junction of MMIC with 500 kHz tone.

Gain of MMIC is a function of temperature.

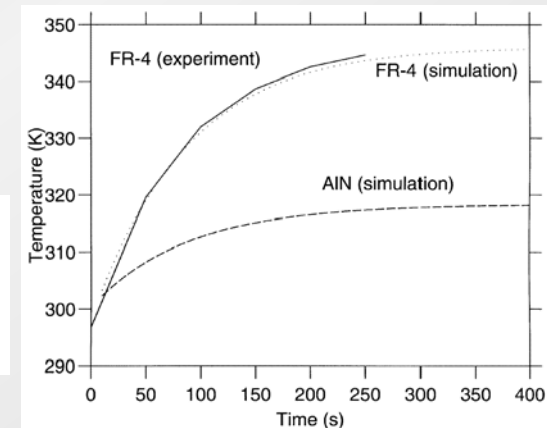
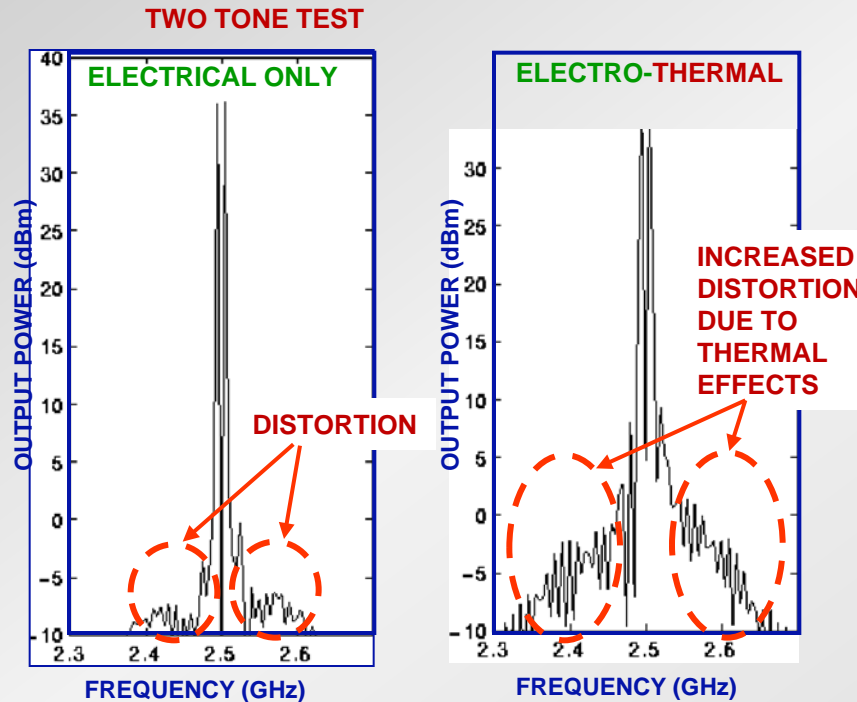
Gain varies with modulation of a signal.

Electro-thermal model construction.



Highest level of integrated global modeling of complex microwave subsystem, to date.

Illustrates impact of thermal effects on total System performance.



- Variations in temperature due to
- turn-on transient (pulsed operation)
 - modulation (variation of signal level)

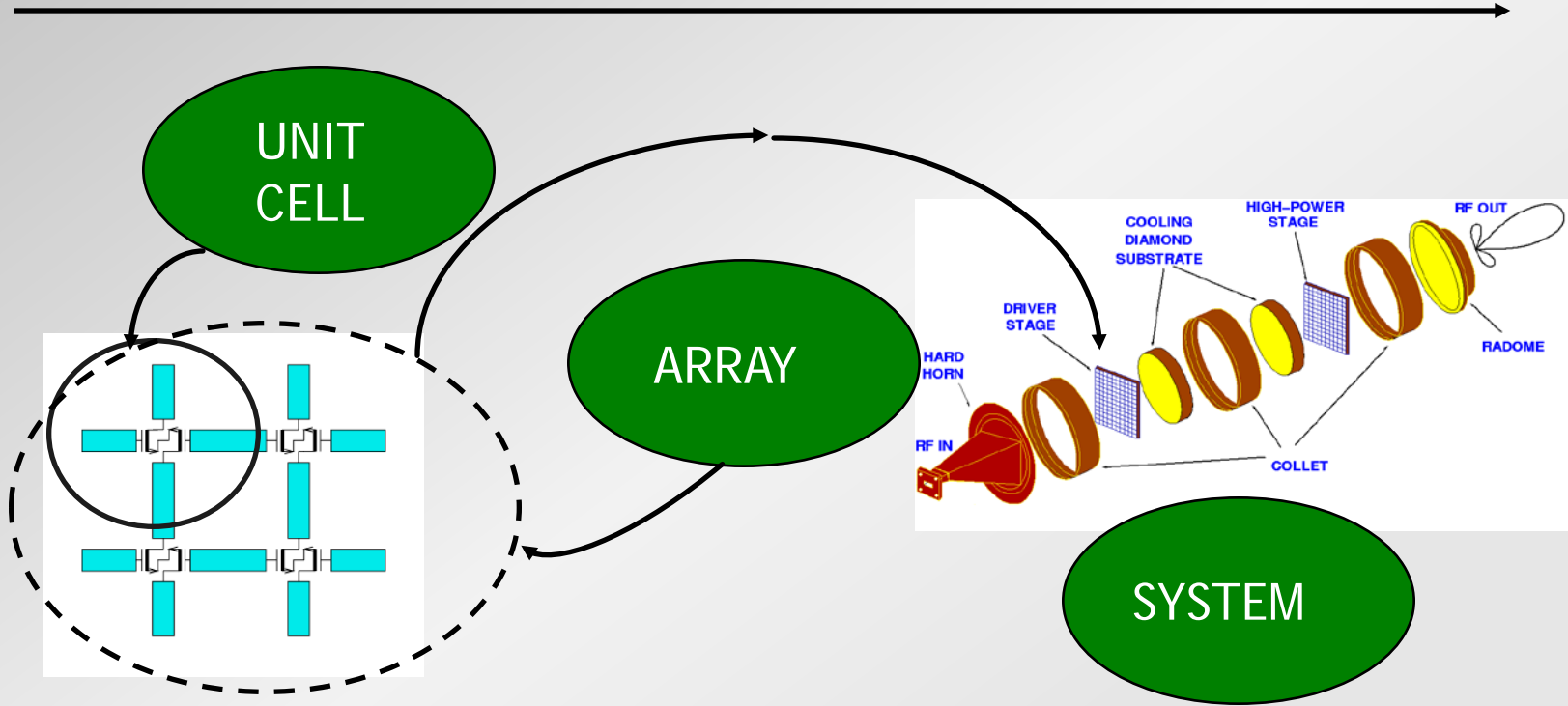
For a Ka band MMIC typically there is a 4 dB drop in gain for a 30 K increase in temperature.

Electro-Thermal Simulation essential to accurate design.

Application: Modeling of a Quasi-Optical Power Combiner

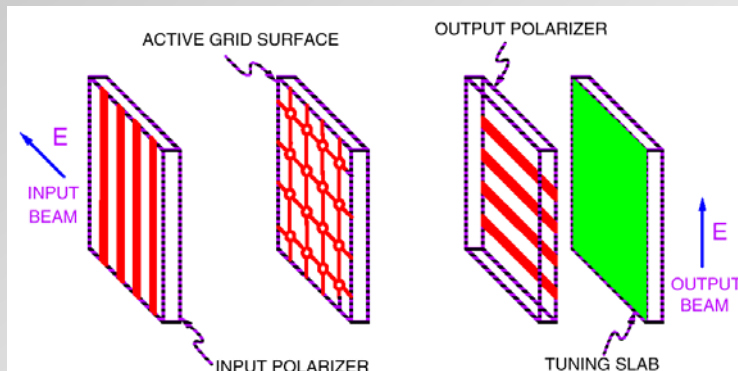
Quasi-Optical Power Combining Amplifier

COMPLETENESS



Essential Problems in CAE of QO Systems

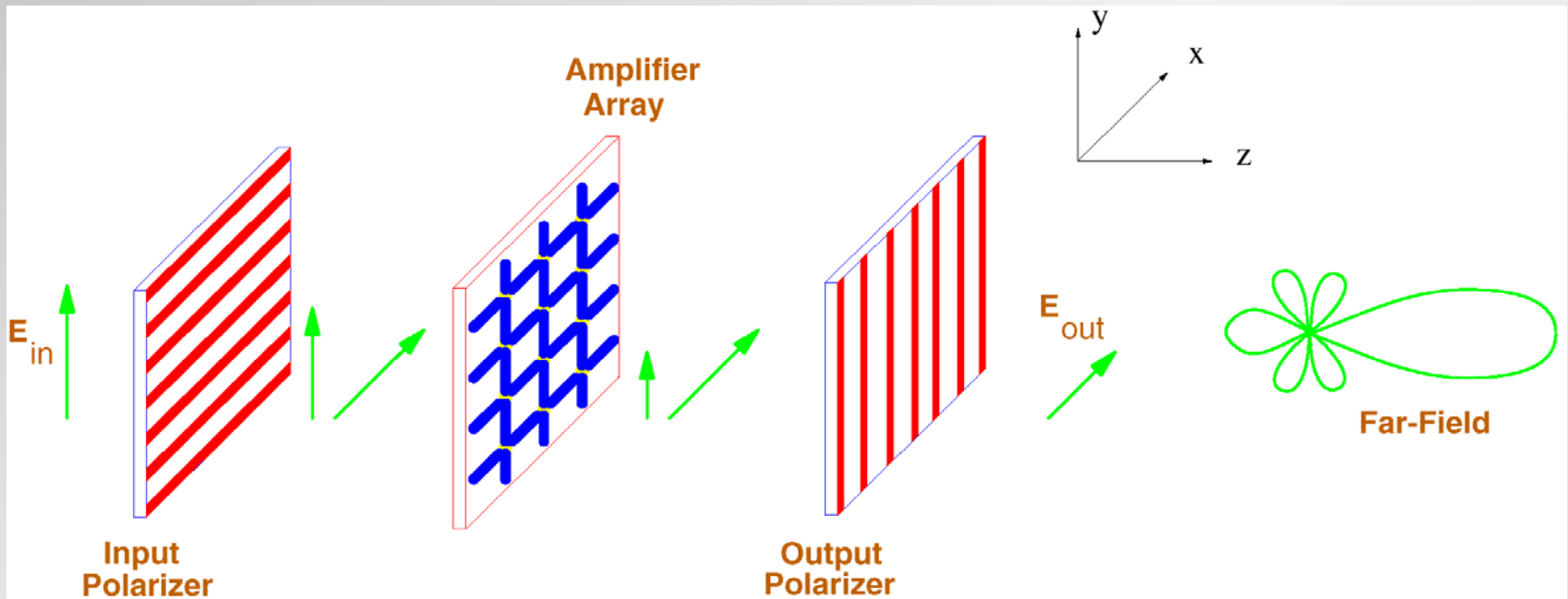
- *Generally There is Not a Common Reference Node*



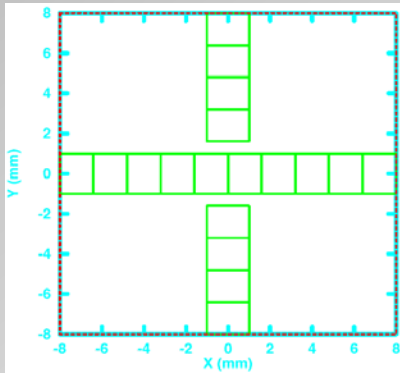
There is No Such Thing as a Node Voltage as Required in Current Microwave Circuit Simulators

- *Concerns Whenever Switching Between Domains*
- *Time--Domain Frequency Domain Conversions: Aliasing etc.*
- *Electrically Large Distributed Structures*
- *Metrology (Model Verification)*
- *A Defined Metrology (Calibration/Measurement Procedure)*
- *Does Not Exist.*

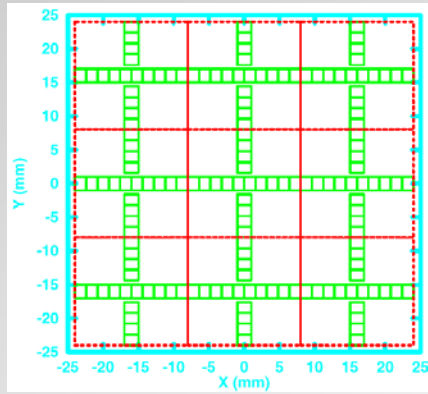
Grid Amplifier System



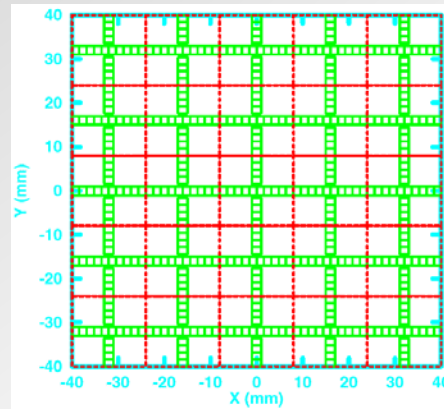
Near-Field Radiation



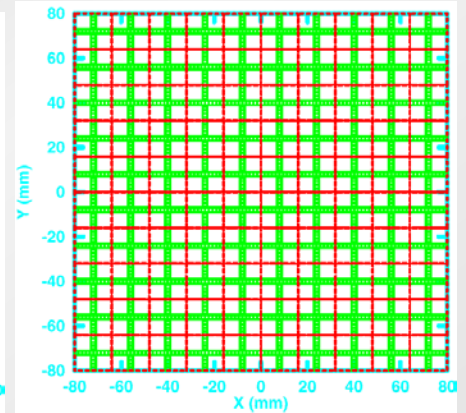
Unit Cell



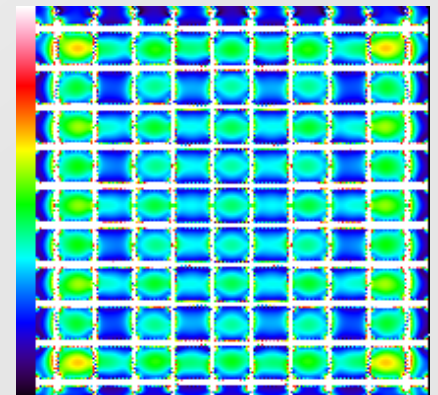
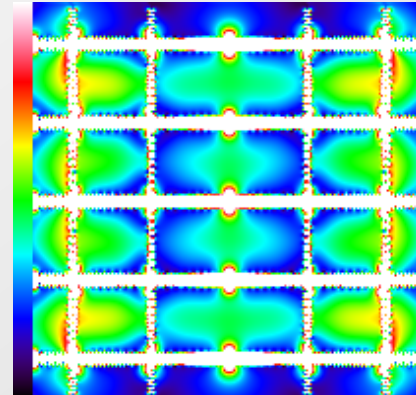
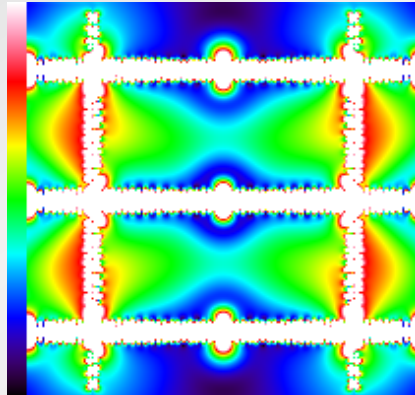
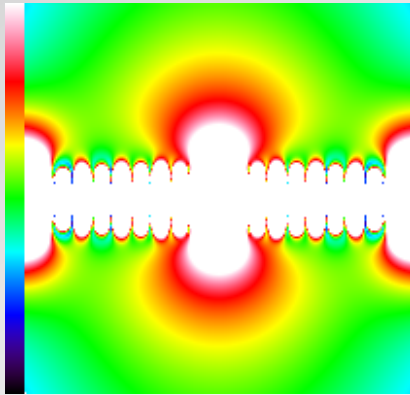
3x3 Grid



5x5 Grid



10x10 Grid

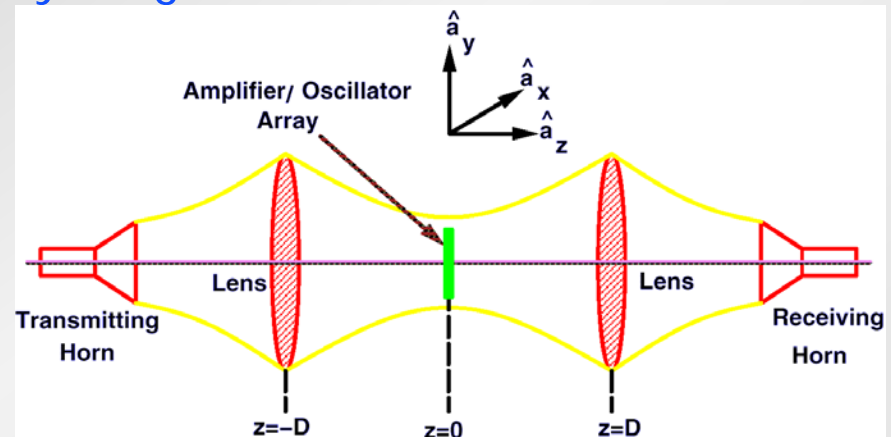


Electromagnetic Modeling of Quasi-Optical Systems

Interfacing Surfaces in Quasi-Optical Systems are Distributed Over Electrically Large Distances

3D Volume Discretization is Inefficient

2D Planar Discretization is Ideal



FEM and FDTD Methods Require 3D Volume Discretization

- Boundary Conditions Required on Volume Terminations
- Large Amounts of Memory and CPU Time Required

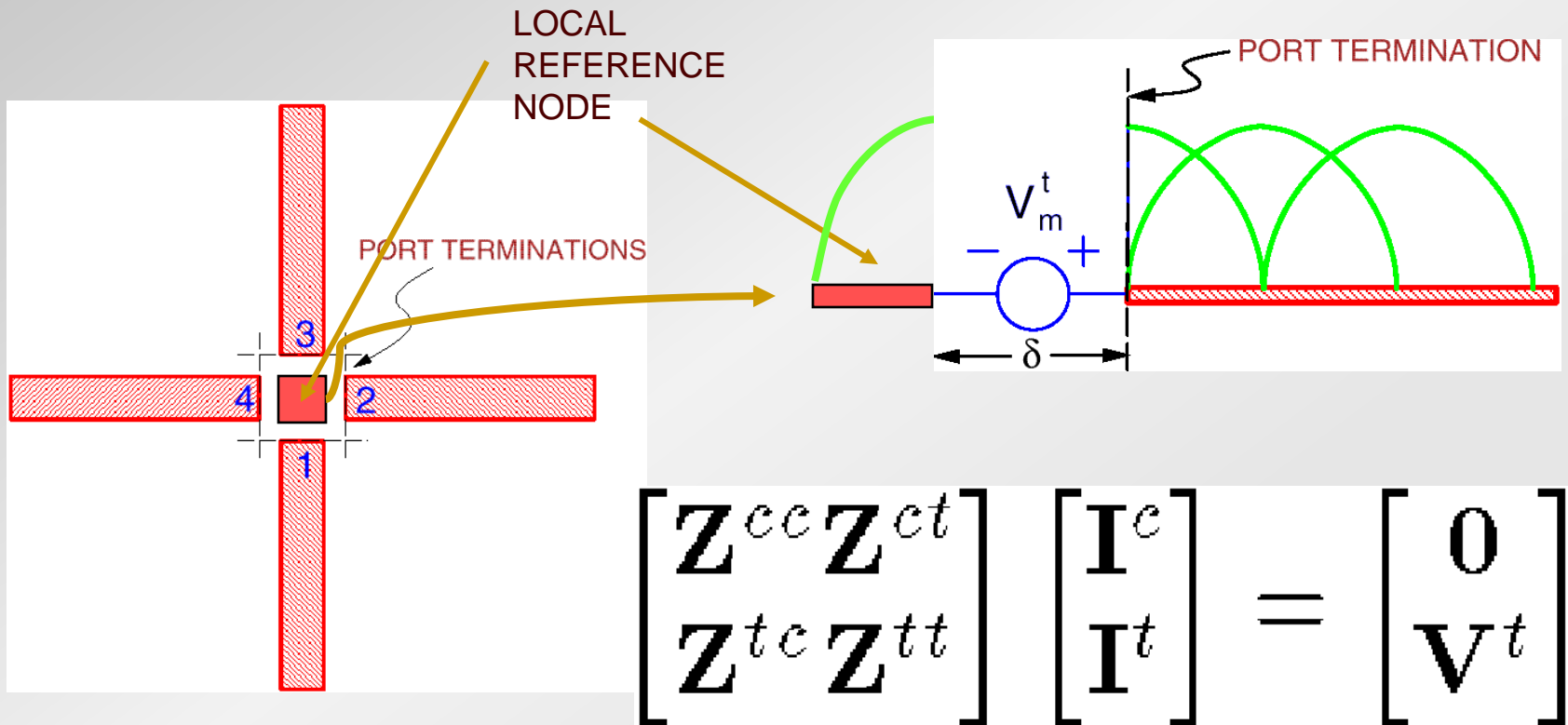
MoM Requires Only 2D Planar Discretization

- Green's Functions Incorporate the Effects of Complete System
- Green's Functions are Interchangeable for Modeling a Variety of Quasi-Optical System Configurations

Nodal Admittance Matrix Determination

Nodal Admittance Description Required in Microwave Circuit Simulators

Process: Guess a node voltage and calculate node current.

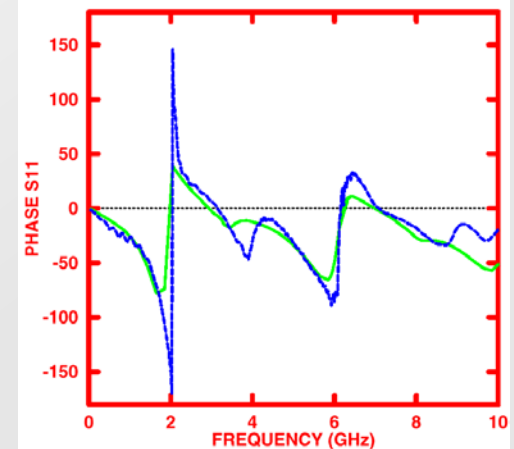
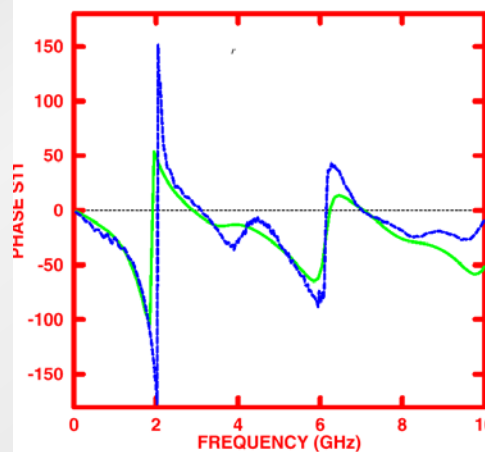
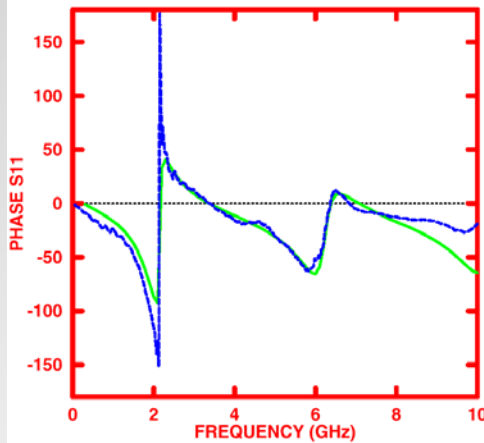
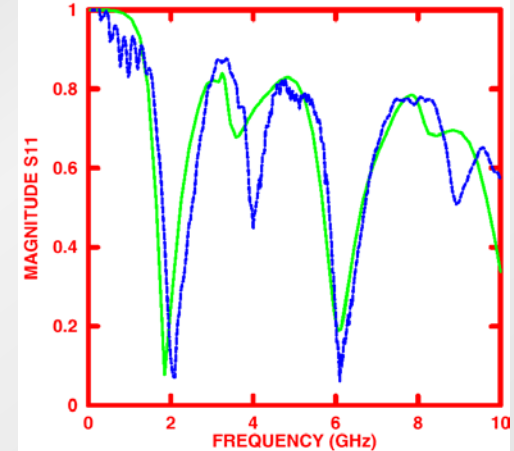
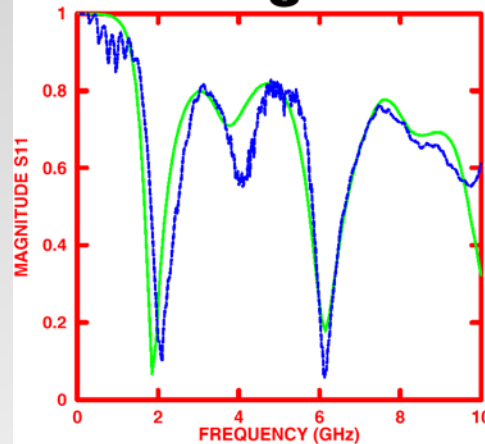
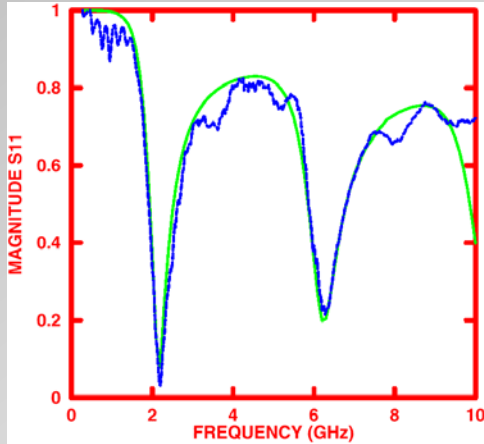


Input Reflection Coefficient

“unit cell”

3 X 3 grid

5 X 5 grid



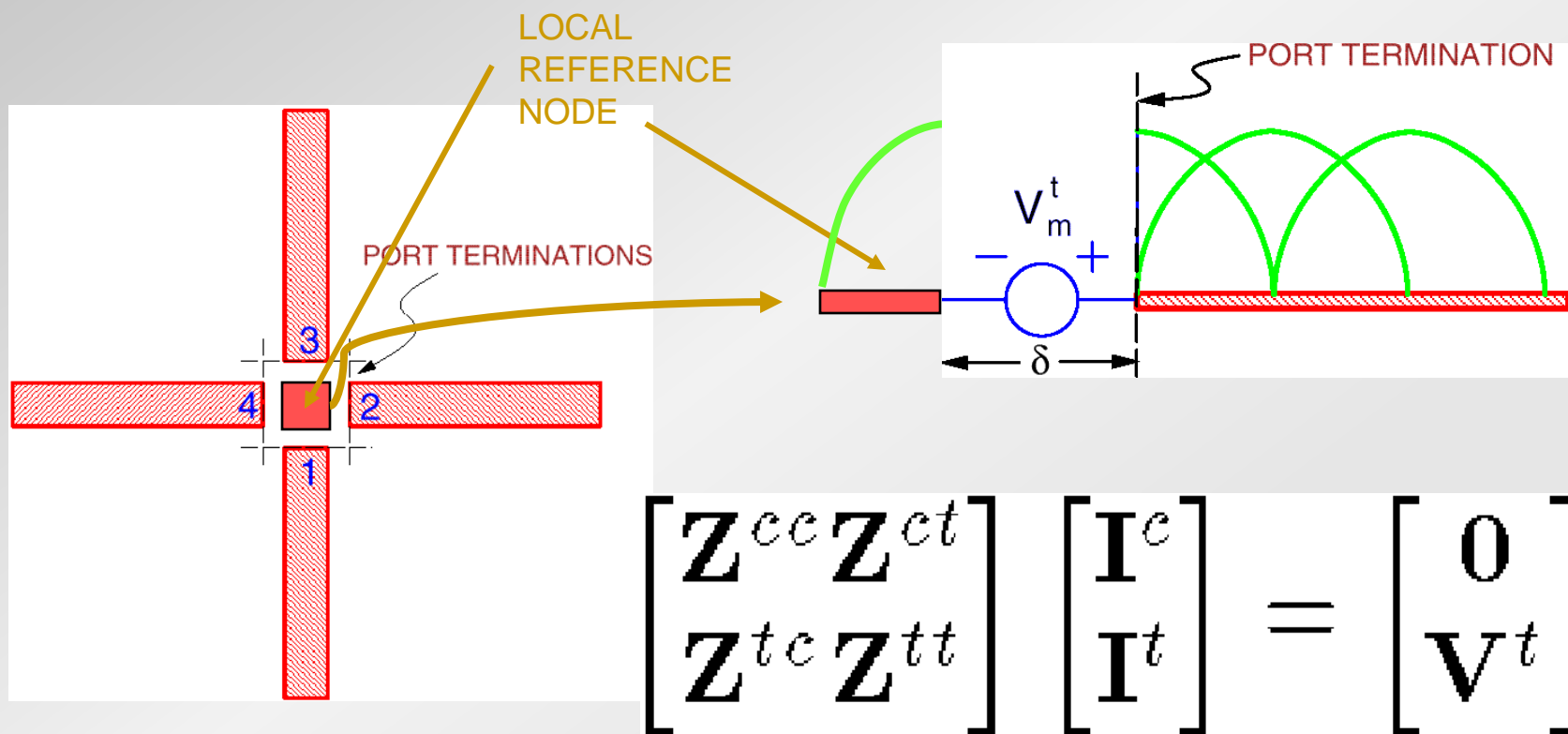
solid line: Circuit/MoM simulation

dashed line: measurement

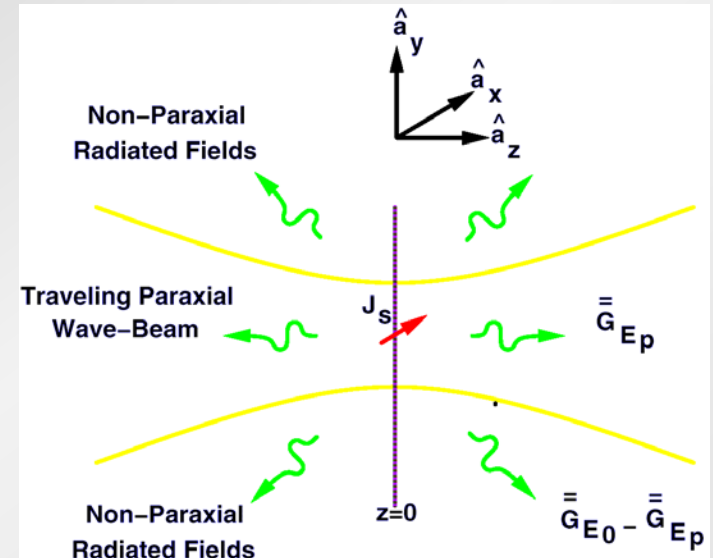
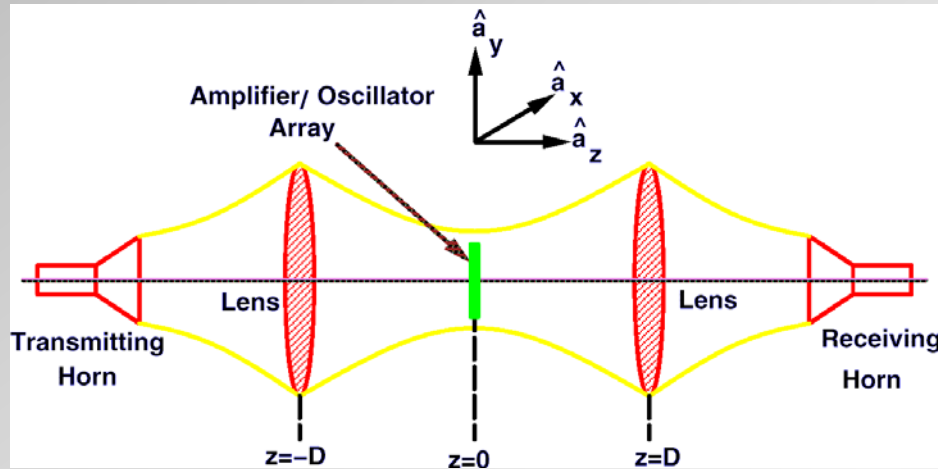
Nodal Admittance Matrix Determination

Nodal Admittance Description Required in Microwave Circuit Simulators

Process: Guess a node voltage and calculate node current.



Development of a Quasi-Optical Green's Function



Green's Function Developed in Piece-wise Fashion

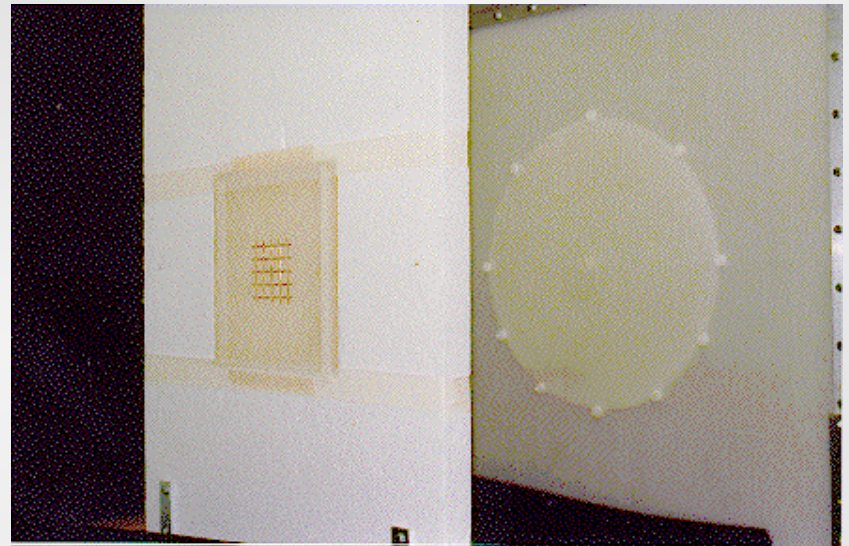
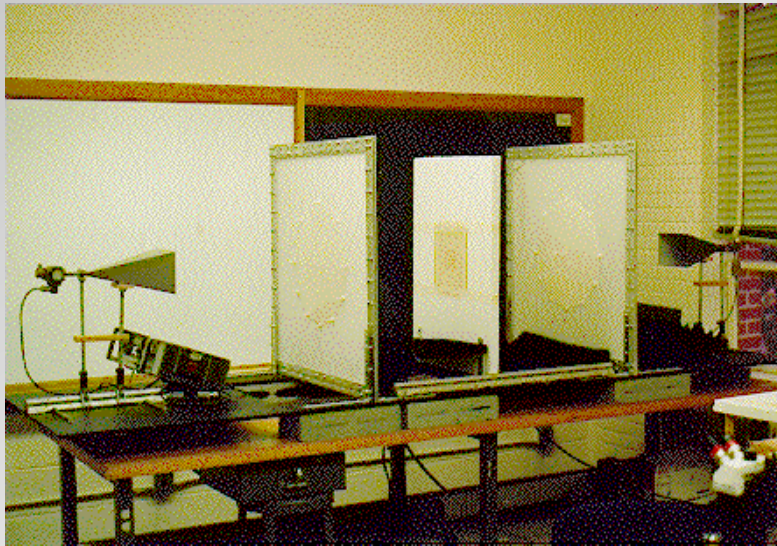
$$\overline{\overline{G}}_E = \overline{\overline{G}}_{Ef} + \overline{\overline{G}}_{EQO}$$

$\overline{\overline{G}}_{Ef} \Rightarrow$ free of any QO components

$\overline{\overline{G}}_{EQO} \Rightarrow$ **QO fields**

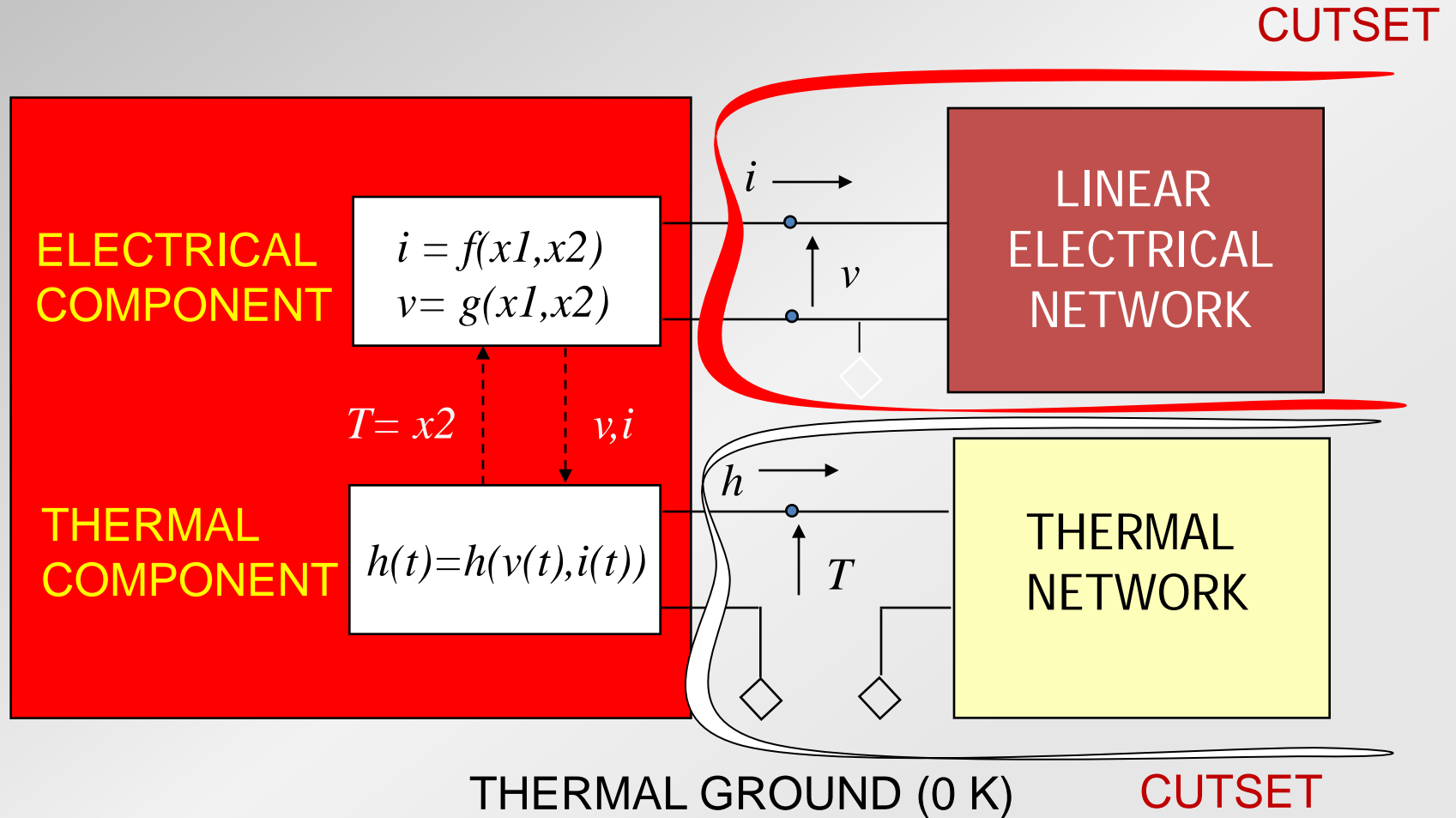
$\overline{\overline{G}}_{Em} \Rightarrow$ modal fields

Measurement Setup



Transistor Model

Nonlinear Electro-Thermal Element



EKV Model (v2.6)

```

void Ekv::eval1(adoublev& x, adoublev& xt, adoublev& y1, adoublev& z1)
{
    if(type == 1)
        eta = 0.5;
    else eta = 0.3333333333333333;

    // Effective gate voltage including reverse short channel effect
    vgprime = type*x[1] - vtoa - deltavRSCE + phiT + gammaa * sqrt(phiT);

    // Effective substrate factor including charge-sharing for short and narrow
    // channels
    // Pinch-off voltage for narrow-channel effect
    vpo1 = vgprime - phiT - gammaa * (sqrt(vgprime + gammaa*gammaa / 4) - gammaa
    / 2);
    condassign(vpo, vgprime, vpo1, -phiT);

    // Effective substrate factor accounting for charge-sharing
    vsprime=0.5*(type*x[2]+phiT+sqrt(pow(type*x[2]+phiT,2) + 16 * vtT*vtT));
    vdprime=0.5*( type*x[0]+phiT+sqrt(pow( type*x[0]+phiT,2) + 16 * vtT*vtT));

    // Pinch-off voltage including short- and narrow-channel effect
    gammao = gammaa - epsilonSi * (leta * (sqrt(vsprime) + sqrt(vdprime))
    / leff - 3 * weta * sqrt(vpo + phiT) / weff) / cox;
    gammaprime = 0.5 * (gammao + sqrt(gammao*gammao + 0.1 * vtT));
    vp1 = vgprime - phiT - gammaprime * (sqrt(vgprime+pow(gammaprime / 2,2)) -
    gammaprime / 2);
    condassign(vp, vgprime, vp1, -phiT);

    // Slope factor
    n = 1 + gammaa / (2 * sqrt(vp + phiT + 4 * vtT));

    // Forward normalized current
    i_f=log(1+exp((vp-type*x[2])/(2*vtT)))*log(1+exp((vp-type*x[2])/(2*vtT)));

    // Velocity saturation voltage
    vdss = vc * (sqrt(0.25 + vtT * sqrt(i_f) / vc) - 0.5);

```

```

// Drain-to-source saturation voltage for reverse normalized current
vdssprime = vc * (sqrt(0.25 + vtT * (sqrt(i_f) - 0.75 * log(i_f))/vc) - 0.5) +
vtT * (log(vc / (2 * vtT)) - 0.6);

// Channel-length modulation
deltav = 4 * vtT * sqrt(lambda * (sqrt(i_f) - vdss / vtT) + 1 / 64);
vds = ( type*x[0] - type*x[2]) / 2;
vip = sqrt(vdss*vdss + deltav*deltav) - sqrt(pow(vds - vdss,2) + deltav*deltav);
deltal = lambda * lc * log(1 + (vds - vip) / (lc * ucritT));

// Equivalent channel length including channel-length modulation and velocity
// saturation
lprime = ns * leff - deltal + (vds + vip) / ucritT;
leq = 0.5 * (lprime + sqrt(lprime*lprime + lmin*lmin));

// Reverse normalized current
irprime = log(1 + exp(((vp - vds - type*x[2] - sqrt(vdssprime*vdssprime +
deltav*deltav) + sqrt((vds-vdssprime)*(vds-vdssprime) + deltav*deltav)) /
vtT) / 2)) * log(1 + exp(((vp - vds - type*x[2] - sqrt(vdssprime*vdssprime +
deltav*deltav) + sqrt((vds-vdssprime)*(vds-vdssprime) + deltav*deltav)) / vtT) / 2));

// Reverse normalized current for mobility model, intrinsic
//charges/capacitances, thermal noise model and NQS time-constant
ir=log(1+exp((vp-type*x[0])/(2*vtT)))*log(1+exp((vp-type*x[0])/(2*vtT)));

// Transconductance factor and mobility reduction due to vertical field
betao = kpa * np * weff / leq;
betaoprime = betao * (1 + cox * qbo / (eo * epsilon_si));

// Simple mobility reduction model
//vpprime = 0.5 * (vp + sqrt(vp*vp + 2* vtT*vtT));

```

```

//beta = betao / (1 + theta * vpprime);

// Quasi-static model equations
// Dynamic model for the intrinsic node charges
nq = 1 + gammaa / (2 * sqrt(vp + phiT + 1e-6));

// Normalized intrinsic node charges
xf = sqrt(0.25 + i_f);
xr = sqrt(0.25 + ir);
qd = -nq * (4 * (3 * xr*xr*xr + 6 * xr*xr * xf + 4 * xr * xf*xf + 2 * xf*xf*xf)
           / (15 * pow(xf + xr,2)) - 0.5);
qs = -nq * (4 * (3 * xf*xf*xf + 6 * xf*xf * xr + 4 * xf * xr*xr + 2 * xr*xr*xr)
           / (15 * pow(xf + xr,2)) - 0.5);
qi = qs + qd;
qbl = -gammaa * sqrt(vp + phiT + 1e-6) / vtT - (nq - 1) * qi / nq;
condassign(qb, vpprime, qbl, -vpprime / vtT);
qg = -qi - qox - qb;

// Rigorous mobility reduction model
beta = betaoprime / (1 + cox * vtT * fabs(qb + eta*qi) / (eo * epsilonsi));

// Specific current
is = 2 * n * beta * vtT*vtT;

// Drain-to-source current
ids = type*is * (i_f - irprime);

// Impact ionization current
vib = type*x[0] - type*x[2] - 2 * ibn * vdss;
idb1 = ids * iba * vib * exp(-ibbT * lc / vib) / ibbT;
condassign(idb, vib, idb1, 0);
id = ids + idb;

```

```
// Total charges
QI = C_ox * vtT * qi;
QB = C_ox * vtT * qb;
QD = C_ox * vtT * qd;
QS = C_ox * vtT * qs;
QG = C_ox * vtT * qg;

y1[0] = type*QD;
y1[1] = type*QG;
y1[2] = type*QS;

// Assign DC currents
z1[0] = id;    //DC Drain current
z1[1] = 0.0;  //DC Gate current
z1[2] = -id;  //DC Source current

// Assign known output voltages
z1[3] = x[0]; // vdb
z1[4] = x[1]; // vgb
z1[5] = x[2]; // vsb
}

void Ekv::eval2(adoublev& dy1, adoublev& z1, adoublev& y2, adoublev& z2)
{
    z2[0] = z1[3]; //Vdb
    z2[1] = z1[4]; //Vgb
    z2[2] = z1[5]; //Vsb

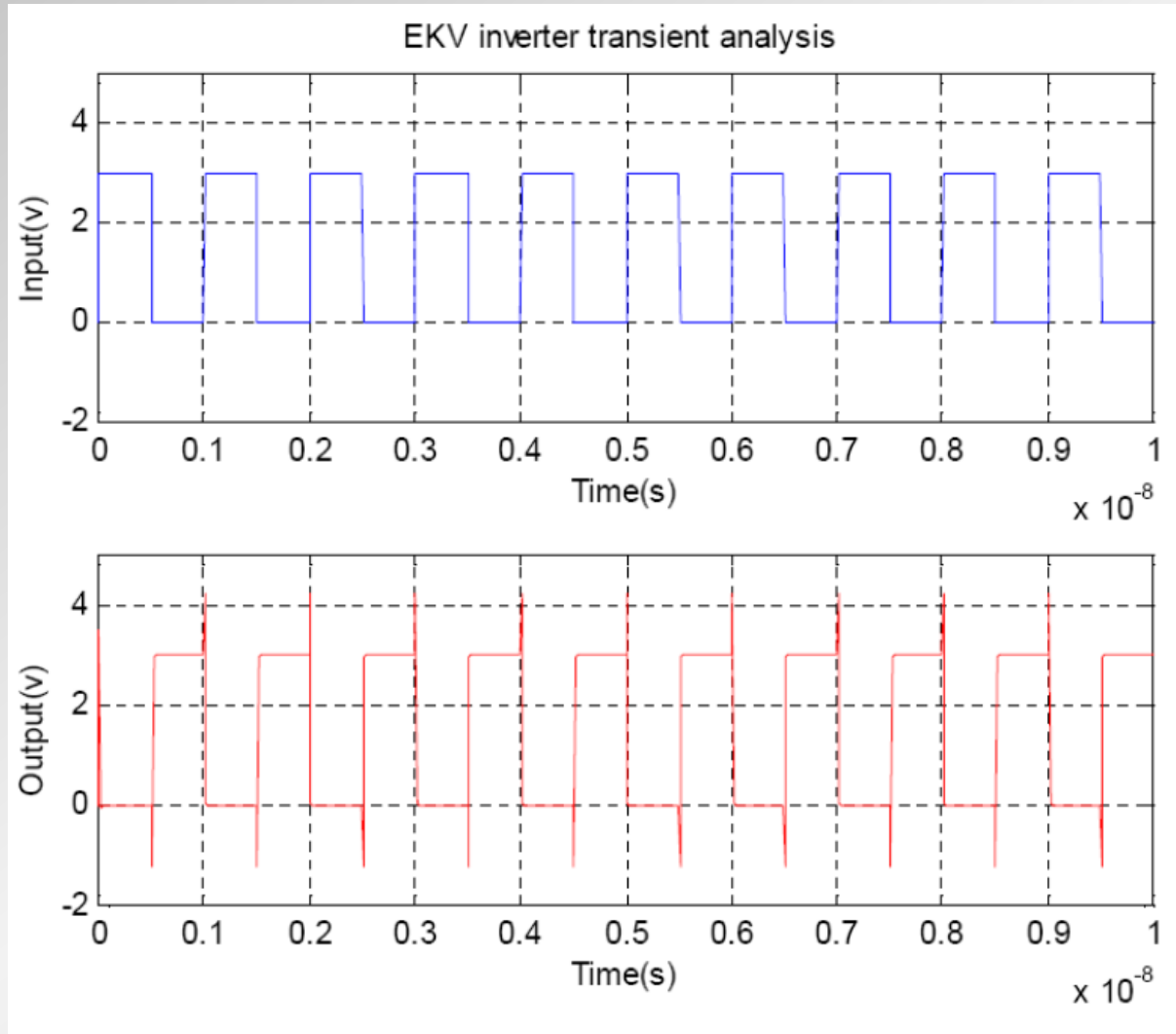
    z2[3] = z1[0] + dy1[0]; //Drain current  Drain charge derivative
    z2[4] = z1[1] + dy1[1]; //Gate current, gate charge derivative
    z2[5] = z1[2] - dy1[2]; //Source current, source charge derivative
}
```

Inverter in fREEDA netlist

```
.tran2 tstop=10e-9 tstep=10e-12
ekv: m1 30 20 10 10 l=1e-6 w=20e-6
+   type=-1
ekv: m2 30 20 0 0 l=1e-6 w=20e-6
vpulse:vgate 20 0 v1=0 v2=3
+   pw=0.5e-9 per=1e-9
vsource:vs 10 0 vdc = 3.0
.out plot term 20 vt in "pulse.in"
.out plot term 30 vt in "pulse.out"
.end
```

Also read SPICE netlist (can be mixed with fREEDA native netlist.)

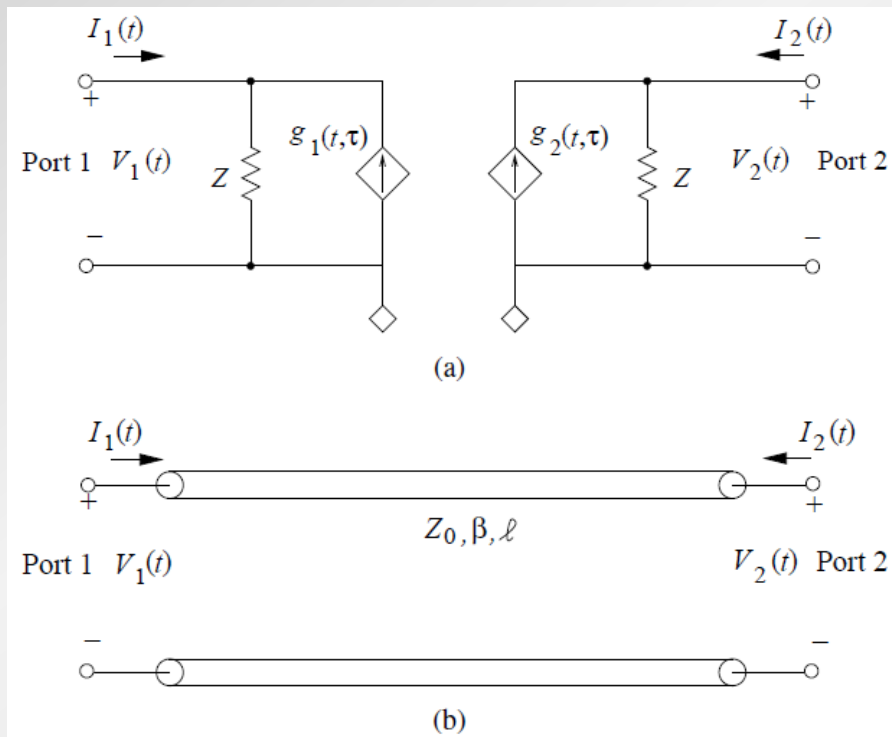
EKV 2.6 Model



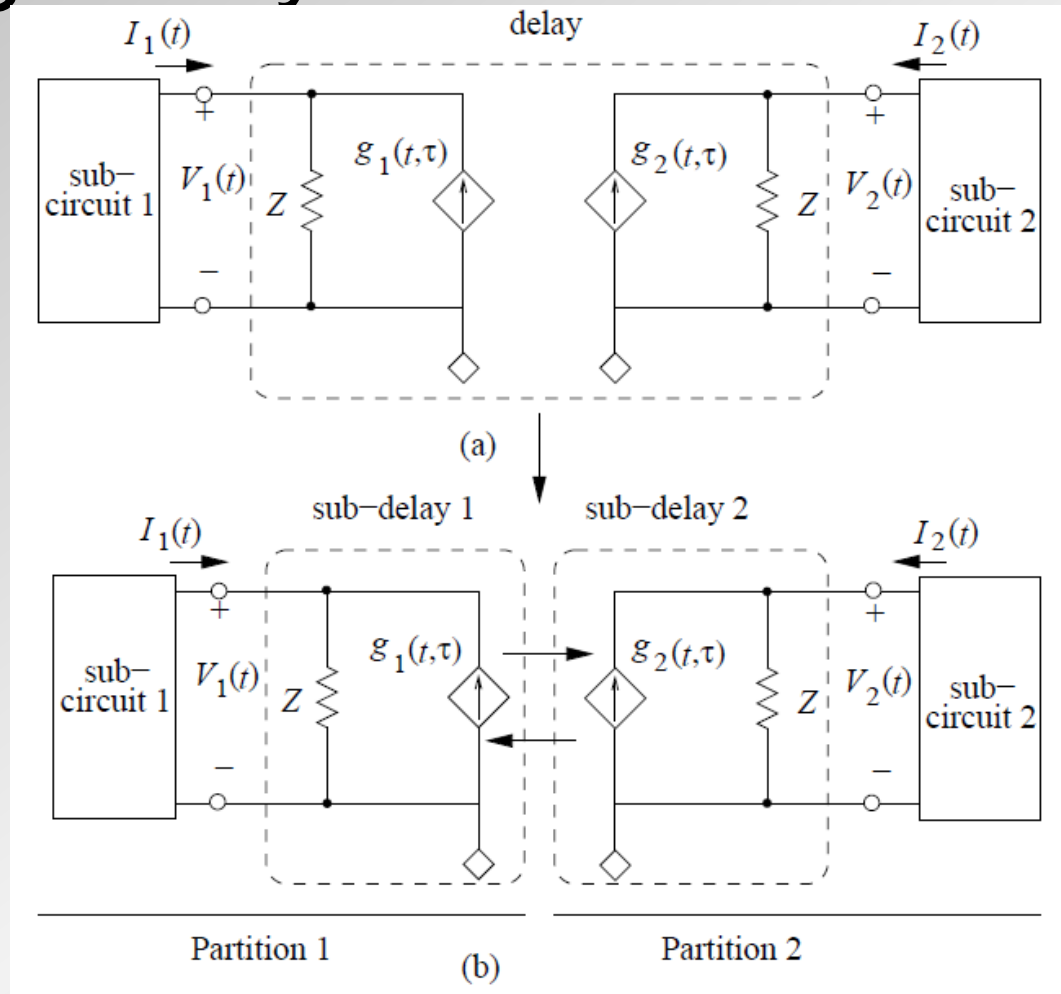
Parallelization

Parallel Transient Circuit Simulation using Delay-Based Partitioning

Shivam Priyadarshi, Christopher S. Saunders, *Student Member, IEEE*, Nikhil M. Kriplani, *Member, IEEE*, Harun Demircioglu, W. Rhett Davis, *Senior Member, IEEE*, and Michael B. Steer, *Fellow, IEEE*

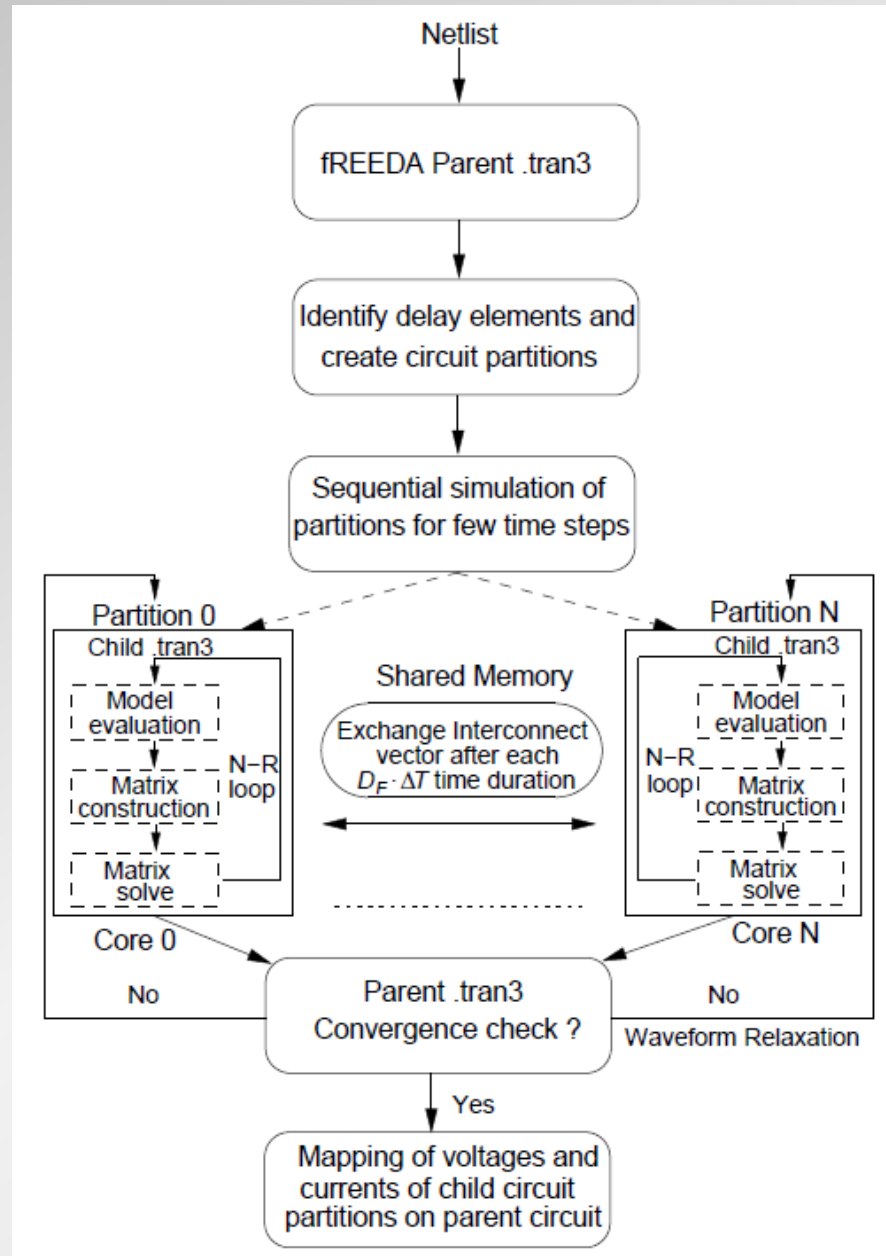


Splitting Delay Element

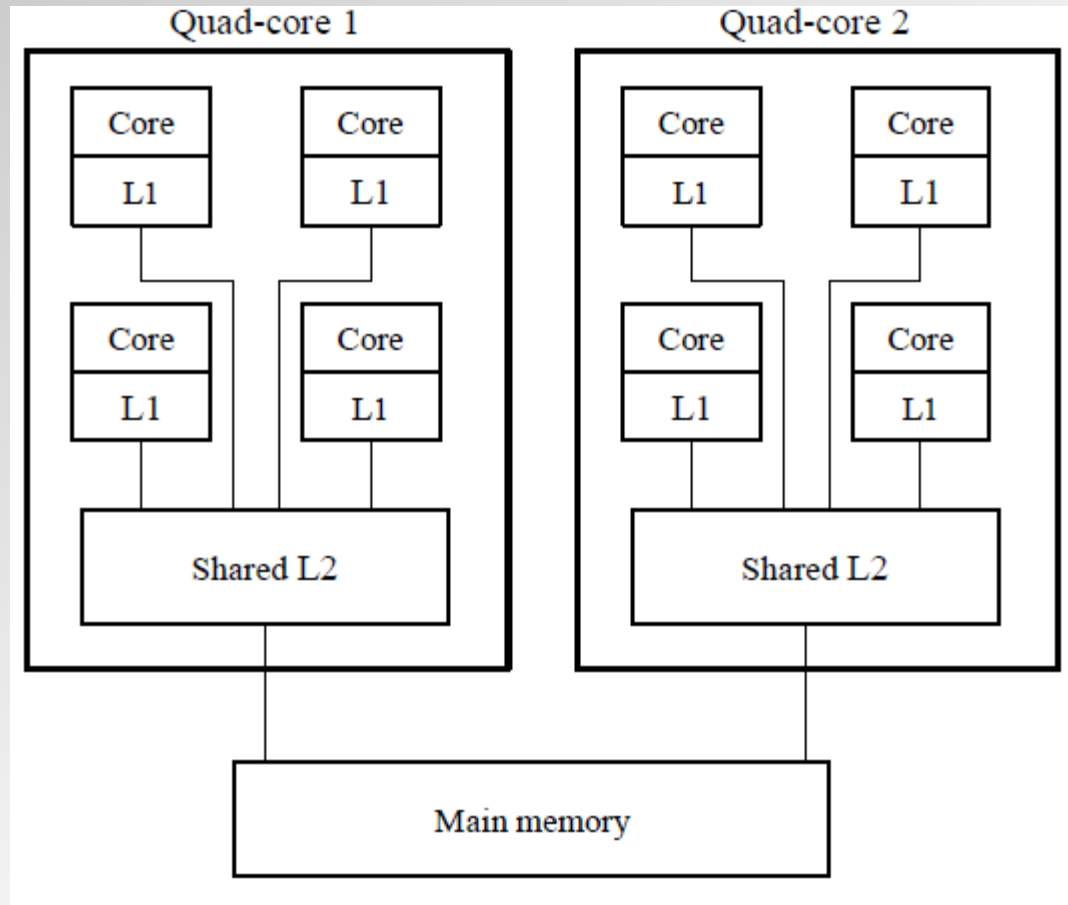


Splitting one delay element, (a), into two sub-delay elements, (b), showing the delay element with two local reference terminals.

Flow



Multi-Processor Implementation



Multiprocessor Implementation

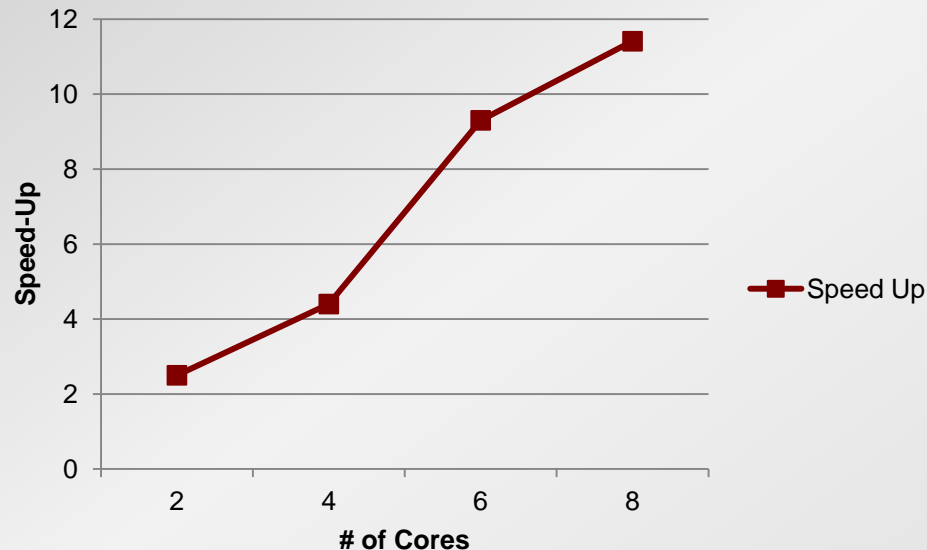
fREEDA Parallelization

Divider Circuit

Chain of 12 Dividers

Number of Non Linear State Variable (ns) : 1238

Number of Linear Element (nm): 229



On a single core most time 68% is in model evaluation. Matrix solve is 11% of the simulation time.

Circuit is partitioned at Delay Elements

Super Linear Speed Up

Load factors (on 4 core) (3-3-3-3)

Load factors (on 6 core) (2-2-2-2-2-2)

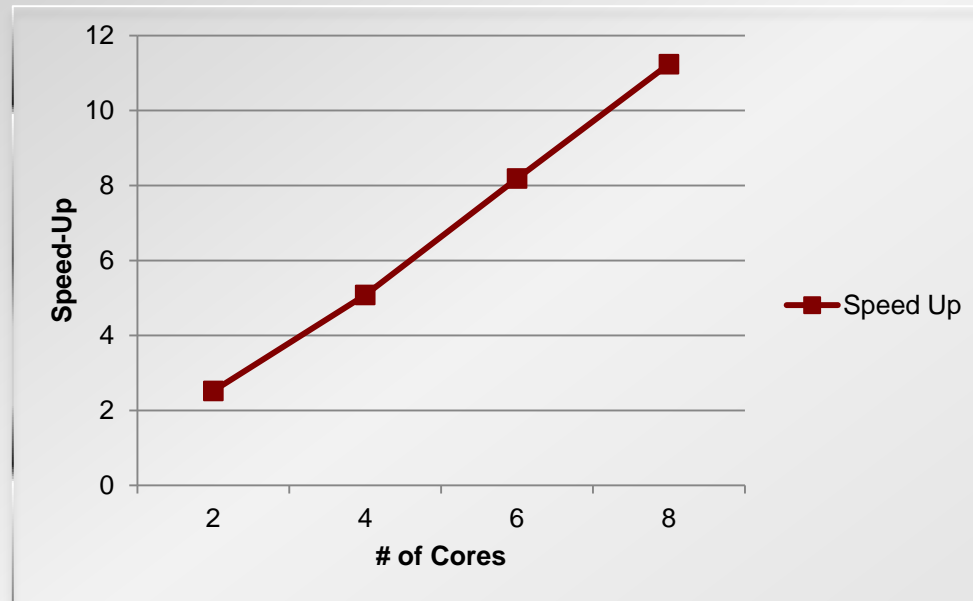
Load factors (on 8 core) (2-2-2-2-1-1-1-1)

fREEDA Parallelization

20-bit Adder

Number of Non Linear State Variable (ns) : 2174

Number of Linear Element (nm): 465

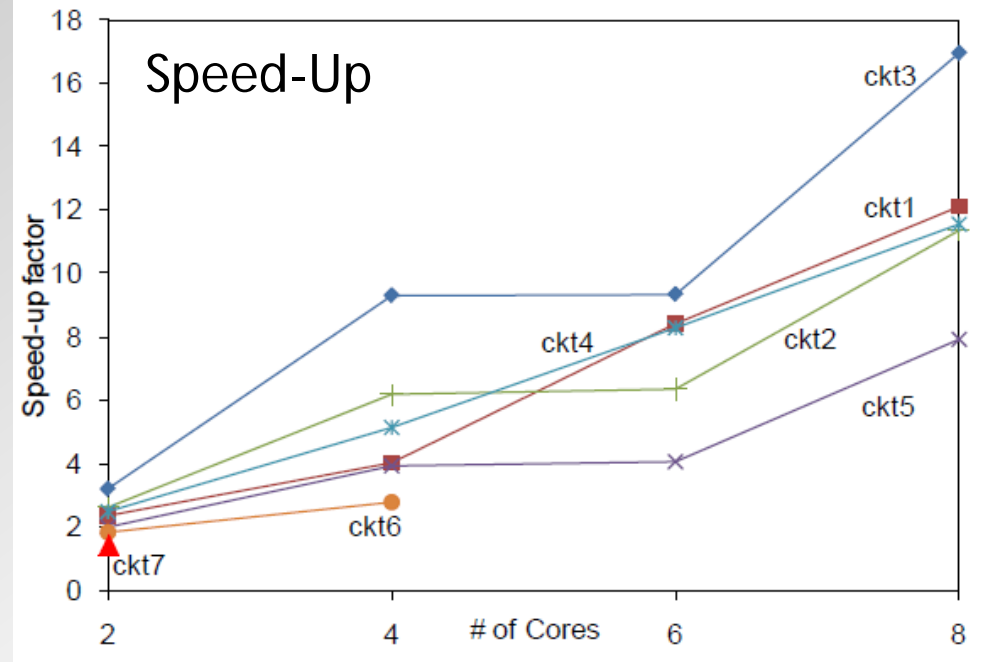


On a single core 54.8% of the time is in model evaluation. Matrix solve is 0.85% of the simulation time.

Circuit is partitioned at Delay Elements
Super Linear Speed Up

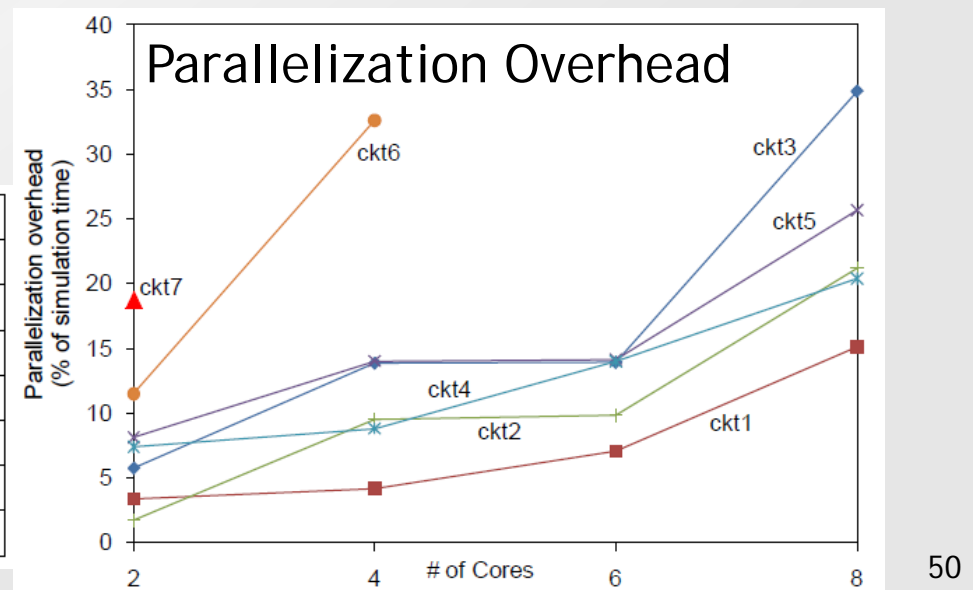
Speed-Up

Circuit	Description	n_m	n_s	T_{stop} (ns)	ΔT (ps)
ckt1	Chain of 12 frequency dividers	229	1238	100	6
ckt2	Chain of 8 electrothermal frequency multipliers (3DIC)	2815	216	1200	10
ckt3	48 Segment soliton line	2024	61	1	0.1
ckt4	20 Bit ripple carry adder	465	2174	10	8
ckt5	Chain of 48 inverters	73	302	10	1
ckt6	8th Order butterworth bandpass filter	89	138	1000	20
ckt7	MMIC LNA	556	6	4	1

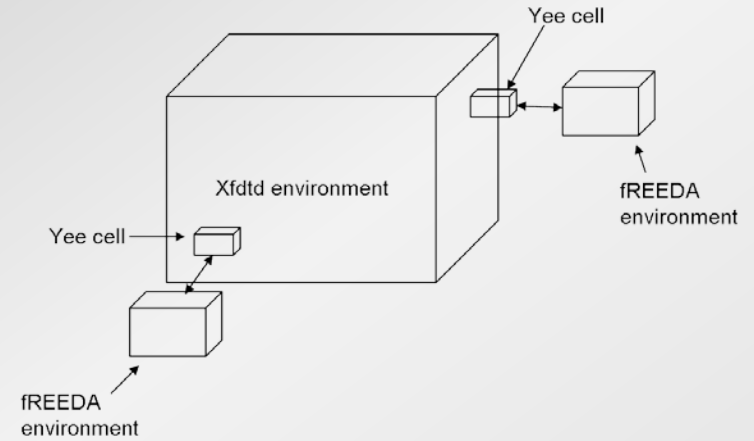
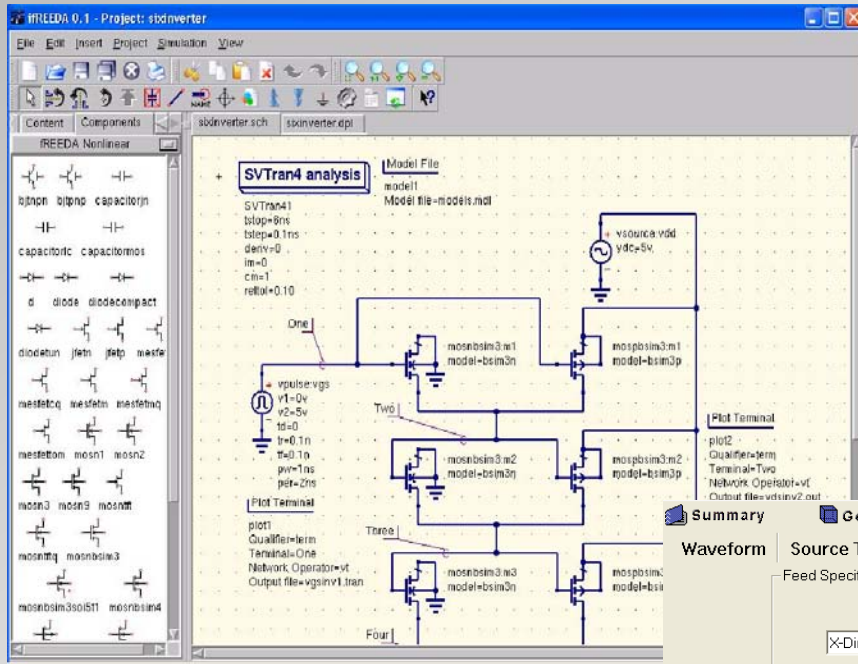


WORKLOAD DISTRIBUTION ACROSS THE CORES

Circuit	2 Core	4 Core	6 Core	8 Core
ckt1	6-6	4-4-2-2	2-2-2-2-2-2	1-1-2-2-2-2-1-1
ckt2	4-4	2-2-2-2	2-1-1-1-1-2	1-1-1-1-1-1-1-1
ckt3	24-24	12-12-12-12	12-12-6-6-6-6	6-6-6-6-6-6-6-6
ckt4	10-10	6-4-6-4	3-3-4-3-3-4	3-3-2-2-3-3-2-2
ckt5	24-24	12-12-12-12	12-12-6-6-6-6	6-6-6-6-6-6-6-6
ckt6	2-2	1-1-1-1	-	-
ckt7	1-1	-	-	-



fREEDA and REMCOM's xFDTD



Summary Geometry Run Parameters Request Results Results

Waveform Source Type Components/Ports Outer Boundary

Feed Specifications

X-Directed

x: 162, y: 28, z: 28

Port

Series Voltage, + Polarity, Parallel Load

Amplitude: 1 (Volts), Phase: 0 (Degrees), Time Delay: 0 (timesteps), Time Delay: 0.000e+000 s, Resistance: 50.000000 (ohms), Capacitance: 3.00 (pF (e-12)), Inductance: 2.00 (nH (e-9))

Component Properties: Edit Properties

Switch at: 60 timesteps, Transition Duration: 60 timesteps

S-Parameter/VSWR Calculation: On, Specify Active Feed: 1

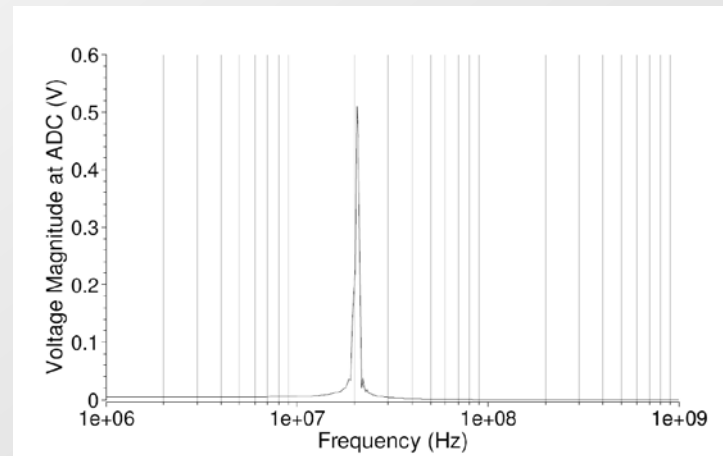
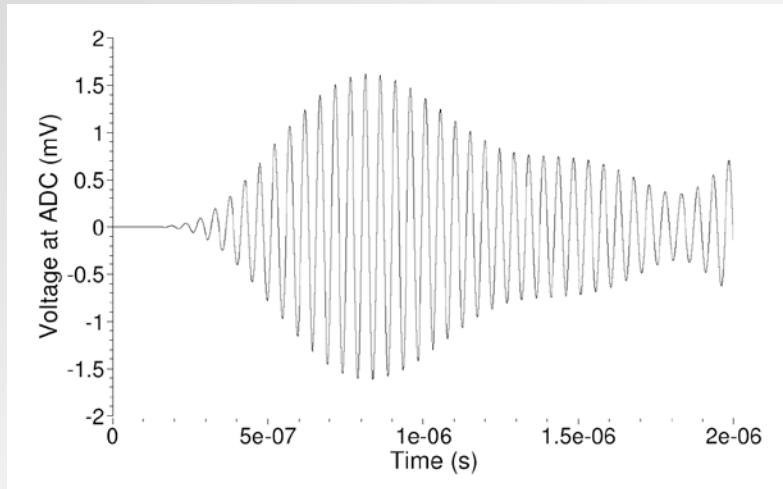
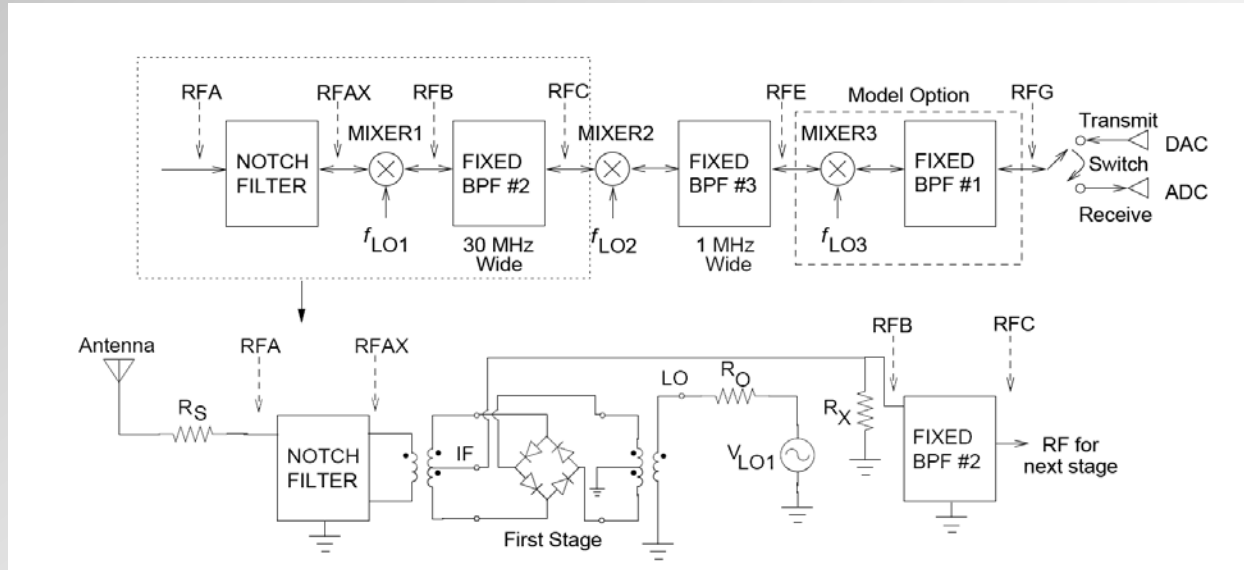
Static Voltages: Enable Solver, Voltage Points

Update Component Add Component Delete Component Delete All Components

#	Port	Type	(Amp/Phase/De...	Dir.(X,Y,Z)	Load/Switch T...	(R,L,C) or Switch Params (Time step,Durati...
1	Y	Voltage	(1.00/0.00/0)	X(162,28,28)	Parallel	(50.00,2.00e-009,3.00e-012)

fREEDA GUI is iFREEDA

Based on QUCS Schematic Capture and Display Front-End (GPL license)



Distributions

- **fREEDA 2**
 - Current on-line distribution
 - Circa November 2010
 - Mostly GPL/LGPL licensed
- **fREEDA 3**
 - Current in-house version
 - Mostly BSD Licensed
 - Some Trilinos packages currently LGPL to be transferred to BSD
 - Compiles cross-platform (Mac, Windows, Unix)
 - Conversion from spice netlist (-like) to XML
 - To Do:
 - Update GUI (iFREEDA)
 - Spice to freedda3 translator
 - Documentation
 - Commercialization
 - Kernal and standard library will be open source
 - Comemrcialization:
 - Model libraries
 - Specialized analyses.

fREEDA

Similar to

Quite Universal Circuit Simulator

Developers

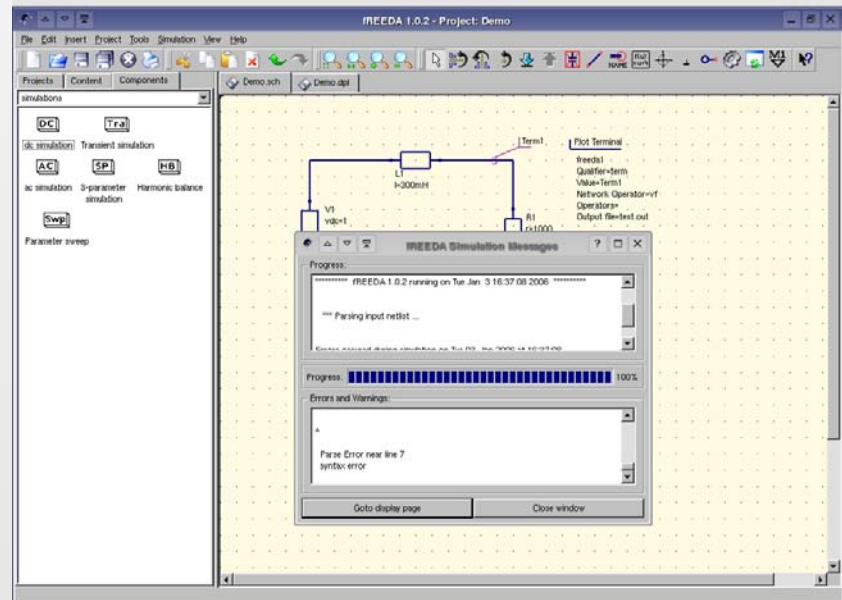
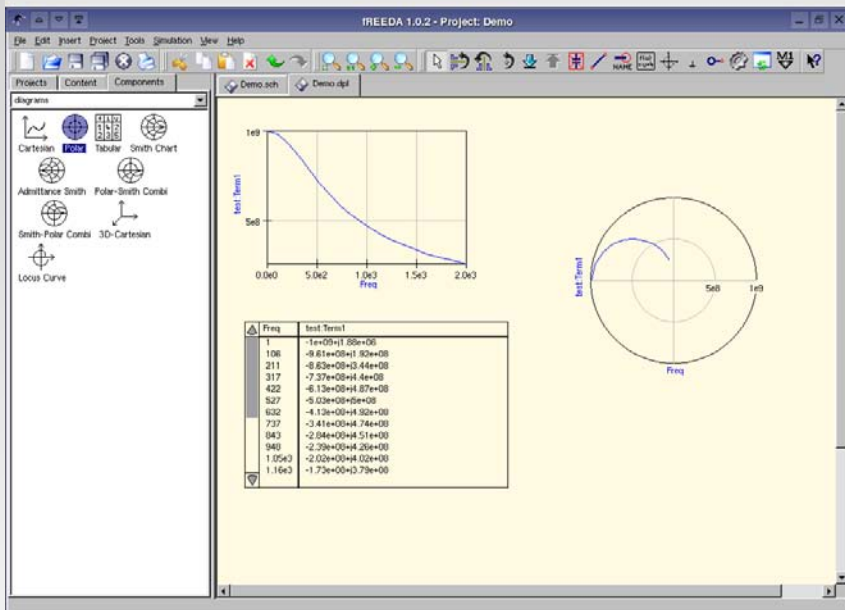
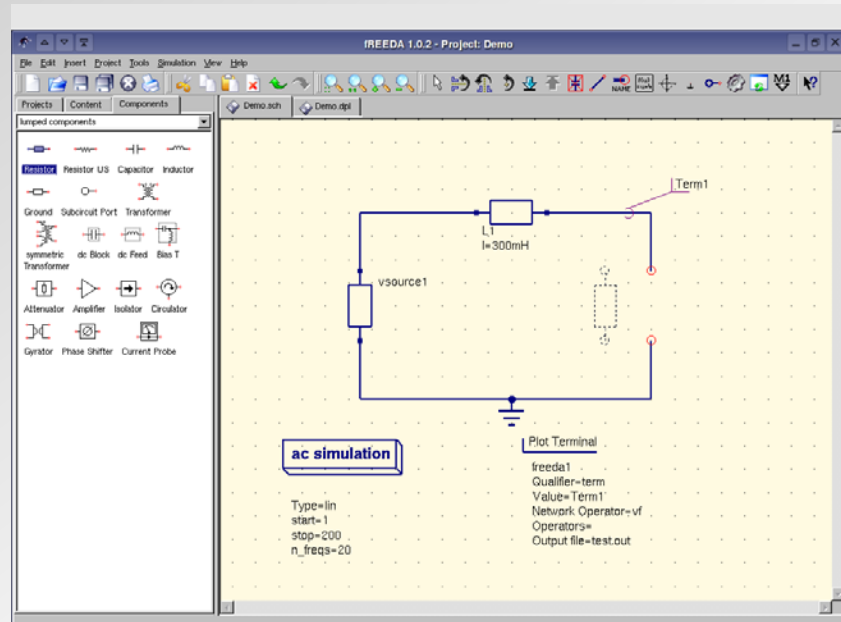
Michael Margraf <michael.margraf@alumni.tu-berlin.de>

owner of the project, GUI programmer

<http://qucs.sourceforge.net>

Based on the QT graphics package:

<http://www.trolltech.com>



fREEDA Commercialization

Open Source / Open Licensing

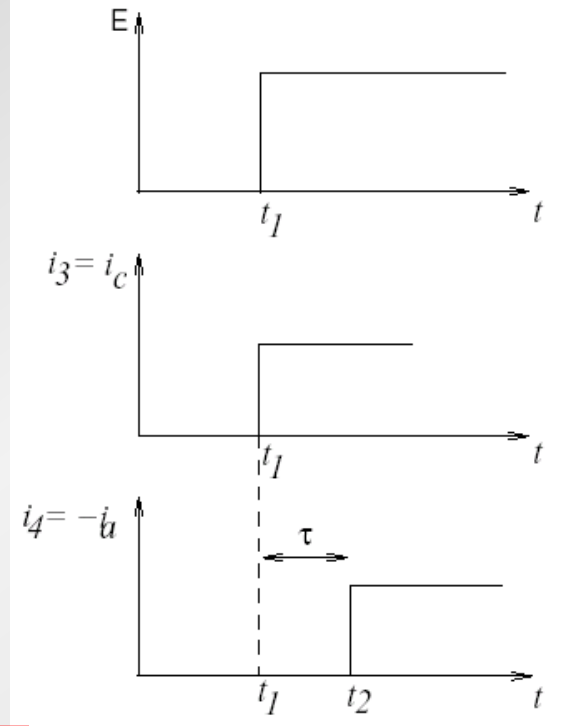
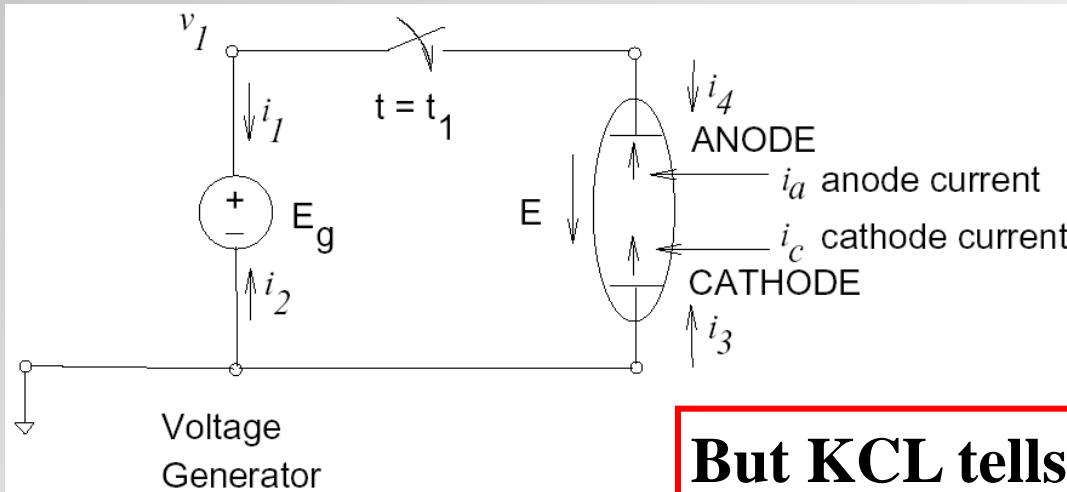
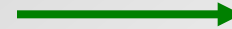
BSD License (Open to companies to do what they want)

Parallel Simulator

Two Commercialization Efforts under way

Modeling Challenge: Non KCL

Two Terminal Element with Delay



But KCL tells us

$$i_4(t) = -i_3(t)$$

$$i_4(t) = -i_3(t - \tau)$$

We do not know how to handle some important aspects of the real world in a circuit simulator!

SIMULATOR TECHNOLOGY IMPOSES A LIMIT ON WHAT CAN BE MODELED

CIRCUITS ARE AN ABSTRACTION

1. C. S. Saunders and M. B. Steer, "Passivity enforcement for admittance models of distributed networks using an inverse eigenvalue method," IEEE Transactions on Microwave Theory and Techniques, In Press.
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10. N. M. Kriplani, D. P. Nackashi, C. J. Amsinck, N. H. Di Spigna, M. B. Steer and P. D. Franzon, R. L. Rick, G. C. Solomon and J. R. Reimers, "Physics-based molecular device model in a transient circuit simulator," Elsevier Science: Chemical Physics, July 11 2006, Vol. 326, Issue 1, Special Issue on The Molecules and Methods of Chemical, Biochemical and Nanoscale Electron Transfer, pp. 188–196.
11. R. Mohan, J. C. Myoung, S. E. Mick, F. P. Hart, K. Chandrasekar, A. C. Cangellaris, P. D. Franzon and M. B. Steer, "Causal reduced-order modeling of distributed structures in a transient circuit simulator," IEEE Trans. Microwave Theory and Tech, Vol. 52, No. 9, Sept. 2004, pp. 2207–2214.
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15. C. E. Christoffersen and M. B. Steer, "State-variable-based transient circuit simulation using wavelets," IEEE Microwave and Guided Waves Letters, Vol. 11. April 2001, pp. 161–163.
16. C. E. Christoffersen, U. A. Mughal, and M. B. Steer, "Object oriented microwave circuit simulation," Int. J. on RF and Microwave Computer Aided Engineering, Vol. 10, Issue 3, May/June 2000, pp. 164–182.
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18. C. E. Christoffersen and M. B. Steer, "Implementation of the local reference node concept for spatially distributed circuits," Int. J. on RF and Microwave Computer Aided Engineering, Vol. 9, No. 5, Sept. 1999, pp. 376–384.
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20. M. N. Abdulla, C. E. Christoffersen, H. M. Gutierrez, P. L. Heron, C. W. Hicks, A. I. Khalil, U. A. Mughal, S. Nakazawa, T. W. Nuteson, J. Patwardhan, S. G. Skaggs, M. A. Summers, S. Wang, and A. B. Yakovlev, "Global modeling of spatially distributed microwave and millimeter-wave systems," IEEE Trans. on Microwave Theory Techniques, June 1999, pp. 830–839

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Summary